

4-BIT SINGLE-CHIP MICROCONTROLLER

DESCRIPTION

The μ PD753017A is one of the 75XL series 4-bit single-chip microcontroller chips and has a data processing capability comparable to that of an 8-bit microcontroller.

It has an on-chip LCD controller/driver with a larger ROM capacity and extended CPU functions compared with the conventional μ PD75316B, and can provide high-speed operation at a low supply voltage of 1.8 V. It can be supplied in a small plastic TQFP package (12 × 12 mm) and is suitable for small sets using LCD panels.

Detailed descriptions of functions are provided in the following document. Be sure to read the document before designing.

μ PD753017 User's Manual : U11282E

FEATURES

- Low voltage operation: $V_{DD} = 1.8$ to 5.5 V
 - Can be driven by two 1.5 V batteries
- On-chip memory
 - Program memory (ROM):
 - 12288 × 8 bits (μ PD753012A)
 - 16384 × 8 bits (μ PD753016A)
 - 24576 × 8 bits (μ PD753017A)
 - Data memory (RAM):
 - 1024 × 4 bits
- Capable of high-speed operation and variable instruction execution time for power saving
 - 0.95, 1.91, 3.81, 15.3 μ s (at 4.19 MHz operation)
 - 0.67, 1.33, 2.67, 10.7 μ s (at 6.0 MHz operation)
 - 122 μ s (at 32.768 kHz operation)
- Internal programmable LCD controller/driver
- Small plastic TQFP (12 × 12 mm)
 - Suitable for small sets such as cameras
- One-time PROM: μ PD75P3018A

APPLICATION

Remote controllers, camera-integrated VCRs, cameras, gas meters, etc.

In this document, unless otherwise specified, the description is made based on μ PD753017A as typical product.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.
Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

ORDERING INFORMATION

	Part number	Package
	μPD753012AGC-XXX-3B9	80-pin plastic QFP (14 × 14 mm, resin thickness 2.7 mm)
★	μPD753012AGC-XXX-8BT	80-pin plastic QFP (14 × 14 mm, resin thickness 1.4 mm)
	μPD753012AGK-XXX-BE9	80-pin plastic TQFP (fine pitch) (12 × 12 mm, resin thickness 1.05 mm)
★	μPD753012AGK-XXX-9EU	80-pin plastic TQFP (fine pitch) (12 × 12 mm, resin thickness 1.00 mm)
	μPD753016AGC-XXX-3B9	80-pin plastic QFP (14 × 14 mm, resin thickness 2.7 mm)
★	μPD753016AGC-XXX-8BT	80-pin plastic QFP (14 × 14 mm, resin thickness 1.4 mm)
	μPD753016AGK-XXX-BE9	80-pin plastic TQFP (fine pitch) (12 × 12 mm, resin thickness 1.05 mm)
★	μPD753016AGK-XXX-9EU	80-pin plastic TQFP (fine pitch) (12 × 12 mm, resin thickness 1.00 mm)
	μPD753017AGC-XXX-3B9	80-pin plastic QFP (14 × 14 mm, resin thickness 2.7 mm)
★	μPD753017AGC-XXX-8BT	80-pin plastic QFP (14 × 14 mm, resin thickness 1.4 mm)
	μPD753017AGK-XXX-BE9	80-pin plastic TQFP (fine pitch) (12 × 12 mm, resin thickness 1.05 mm)
★	μPD753017AGK-XXX-9EU	80-pin plastic TQFP (fine pitch) (12 × 12 mm, resin thickness 1.00 mm)

Remark XXX indicates ROM code suffix.

FUNCTION OUTLINE

Parameter		Function	
Instruction execution time		<ul style="list-style-type: none"> • 0.95, 1.91, 3.81, 15.3 μs (main system clock: at 4.19 MHz operation) • 0.67, 1.33, 2.67, 10.7 μs (main system clock: at 6.0 MHz operation) • 122 μs (subsystem clock: at 32.768 kHz operation) 	
Internal memory	ROM	12288 × 8 bits (μPD753012A)	
		16384 × 8 bits (μPD753016A)	
		24576 × 8 bits (μPD753017A)	
	RAM	1024 × 4 bits	
General purpose register		<ul style="list-style-type: none"> • 4-bit operation: 8 × 4 banks • 8-bit operation: 4 × 4 banks 	
Input/output port	CMOS input	8	On-chip pull-up resistors can be specified by using software: 23
	CMOS input/output	16	
	CMOS output	8	Also used for segment pins
	N-ch open-drain input/output	8	Withstands 13 V, on-chip pull-up resistors can be specified by using mask option
	Total	40	
LCD controller/driver		<ul style="list-style-type: none"> • Segment number selection : 24/28/32 segments (can be changed to CMOS output port in 4 time-unit; max. 8) • Display mode selection : Static, 1/2 duty (1/2 bias), 1/3 duty (1/2 bias), 1/3 duty (1/3 bias), 1/4 duty (1/3 bias) <p>On-chip split resistor for LCD drive can be specified by using mask option</p>	
Timer		5 channels <ul style="list-style-type: none"> • 8-bit timer/event counter: 3 channels (can be used for 16-bit timer/event counter, carrier generator, timer with gate) • Basic interval timer/watchdog timer: 1 channel • Watch timer: 1 channel 	
Serial interface		<ul style="list-style-type: none"> • 3-wire serial I/O mode ... MSB or LSB can be selected for transferring first bit • 2-wire serial I/O mode • SBI mode 	
Bit sequential buffer		16 bits	
Clock output (PCL)		<ul style="list-style-type: none"> • Φ, 524, 262, 65.5 kHz (main system clock: at 4.19 MHz operation) • Φ, 750, 375, 93.8 kHz (main system clock: at 6.0 MHz operation) 	
Buzzer output (BUZ)		<ul style="list-style-type: none"> • 2, 4, 32 kHz (main system clock: at 4.19 MHz operation or subsystem clock: at 32.768 kHz operation) • 2.93, 5.86, 46.9 kHz (main system clock: at 6.0 MHz operation) 	
Vectored interrupt		External: 3, Internal: 5	
Test input		External: 1, Internal: 1	
System clock oscillator		<ul style="list-style-type: none"> • Ceramic or crystal oscillator for main system clock oscillation • Crystal oscillator for subsystem clock oscillation 	
Standby function		STOP/HALT mode	
Power supply voltage		V _{DD} = 1.8 to 5.5 V	
Package		<ul style="list-style-type: none"> • 80-pin plastic QFP (14 × 14 mm) • 80-pin plastic TQFP (fine pitch) (12 × 12 mm) 	

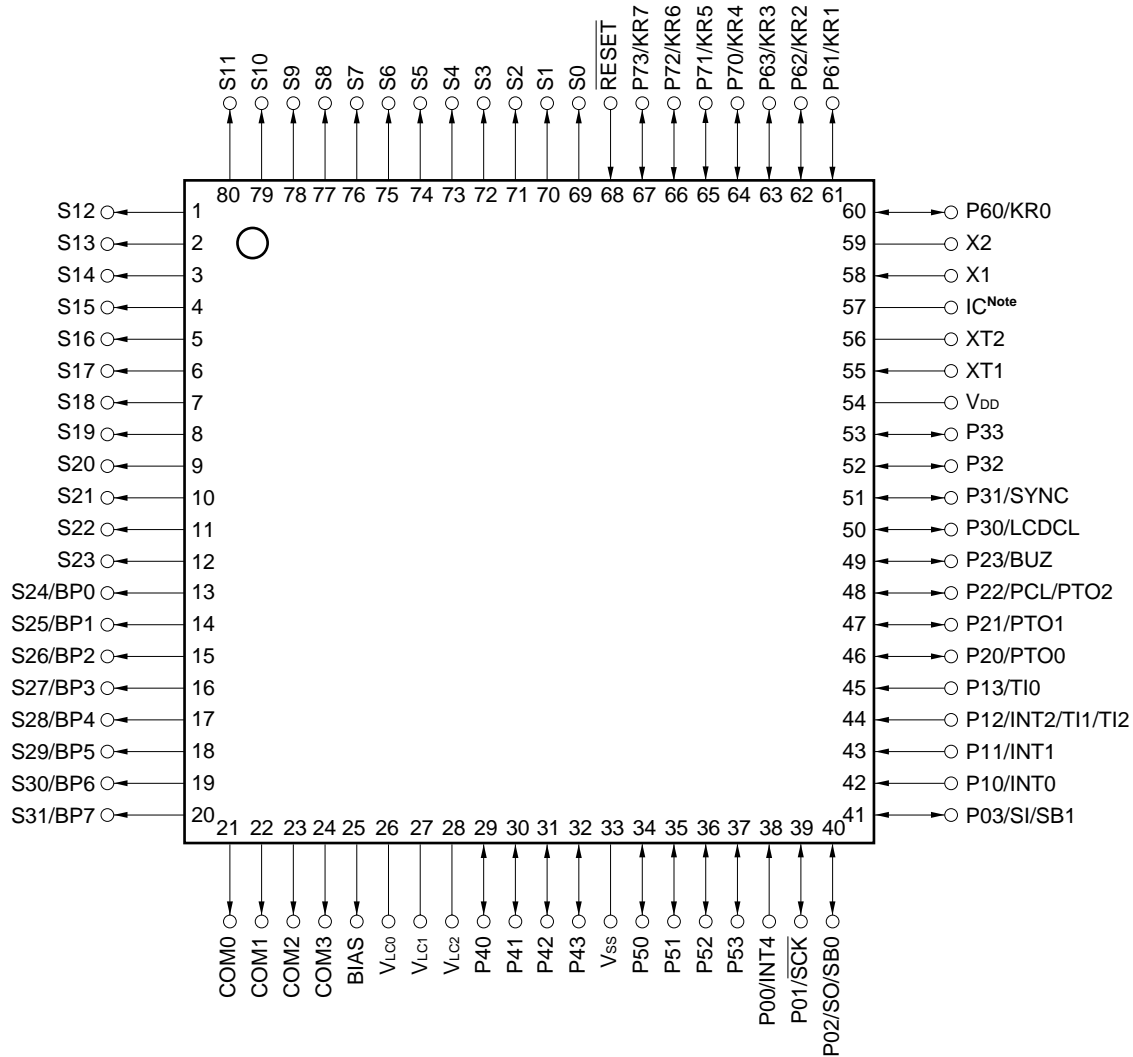
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1. PIN CONFIGURATION (Top View)

- 80-pin plastic QFP (14 × 14 mm)
- ★ μPD753012AGC-XXX-3B9, 753012AGC-XXX-8BT, 753016AGC-XXX-3B9, 753016AGC-XXX-8BT
μPD753017AGC-XXX-3B9, 753017AGC-XXX-8BT
- 80-pin plastic TQFP (fine pitch) (12 × 12 mm)
- ★ μPD753012AGK-XXX-BE9, 753012AGK-XXX-9EU, 753016AGK-XXX-BE9, 753016AGK-XXX-9EU
μPD753017AGK-XXX-BE9, 753017AGK-XXX-9EU

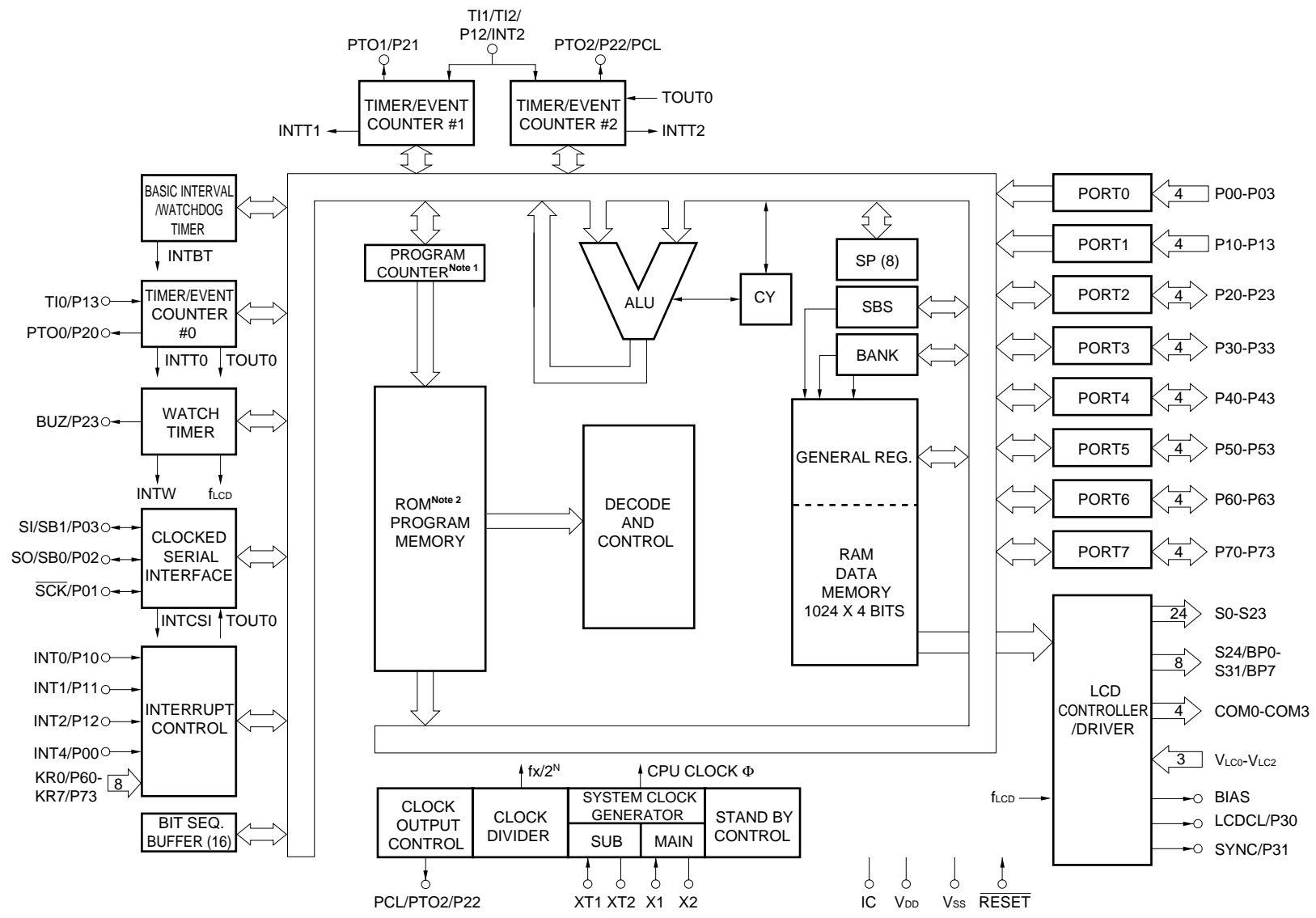


Note Connect the IC (Internally Connected) pin directly to VDD.

Pin Identification

BIAS	: LCD Power Supply Bias Control	PCL	: Programmable Clock
BP0-BP7	: Bit Port	PTO0-PTO2	: Programmable Timer Output 0-2
BUZ	: Buzzer Clock	$\overline{\text{RESET}}$: Reset Input
COM0-COM3	: Common Output 0-3	S0-S31	: Segment Output 0-31
IC	: Internally Connected	SB0, SB1	: Serial Bus 0, 1
INT0, INT1, INT4	: External Vectored Interrupt 0, 1, 4	$\overline{\text{SCK}}$: Serial Clock
INT2	: External Test Input 2	SI	: Serial Input
KR0-KR7	: Key Return	SO	: Serial Output
LCDCL	: LCD Clock	SYNC	: LCD Synchronization
P00-P03	: Port 0	Ti0-Ti2	: Timer Input 0-2
P10-P13	: Port 1	V _{DD}	: Positive Power Supply
P20-P23	: Port 2	V _{LC0-V_{LC2}}	: LCD Power Supply 0-2
P30-P33	: Port 3	V _{SS}	: Ground
P40-P43	: Port 4	X1, X2	: Main System Clock Oscillation 1, 2
P50-P53	: Port 5	XT1, XT2	: Subsystem Clock Oscillation 1, 2
P60-P63	: Port 6		
P70-P73	: Port 7		

2. BLOCK DIAGRAM



- Notes**
1. μPD753012A and 753016A have a 14-bit configuration, and μPD753017A has a 15-bit configuration.
 2. Capacity of the ROM depends on the product.

3. PIN FUNCTION

3.1 Port Pins (1/2)

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★
★

Pin Name	I/O	Alternate Function	Function	8-bit I/O	After Reset	I/O Circuit Type ^{Note 1}
P00	Input	INT4	4-bit input port (PORT0). For P01 to P03, connection of on-chip pull-up resistors can be specified by software in 3-bit units.	No	Input	
P01		$\overline{\text{SCK}}$				<F>-A
P02		SO/SB0				<F>-B
P03		SI/SB1				<M>-C
P10	Input	INT0	4-bit input port (PORT1). Connection of on-chip pull-up resistors can be specified by software in 4-bit units. Only P10/INT0 can select noise elimination circuit.	No	input	-C
P11		INT1				
P12		T11/T12/INT2				
P13		T10				
P20	I/O	PTO0	4-bit input/output port (PORT2). Connection of on-chip pull-up resistors can be specified by software in 4-bit units.	No	Input	E-B
P21		PTO1				
P22		PCL/PTO2				
P23		BUZ				
P30	I/O	LCDCL	Programmable 4-bit input/output port (PORT3). This port can be specified for input/output bit-wise. Connection of on-chip pull-up resistor can be specified by software in 4-bit units.	No	Input	E-B
P31		SYNC				
P32		–				
P33		–				
P40-P43 ^{Note 2}	I/O	–	N-ch open-drain 4-bit input/output port (PORT4). A pull-up resistor can be contained bit-wise (mask option). Withstand voltage is 13 V in open-drain mode.	Yes	High level (when pull-up resistors are provided) or high impedance	M-D
P50-P53 ^{Note 2}		–				

- Notes**
1. Circuit types enclosed in brackets indicate the Schmitt trigger input.
 2. If on-chip pull-up resistors are not specified by mask option (when used as N-ch open-drain input port), low level input leakage current increases when input or bit manipulation instruction is executed.

3.1 Port Pins (2/2)

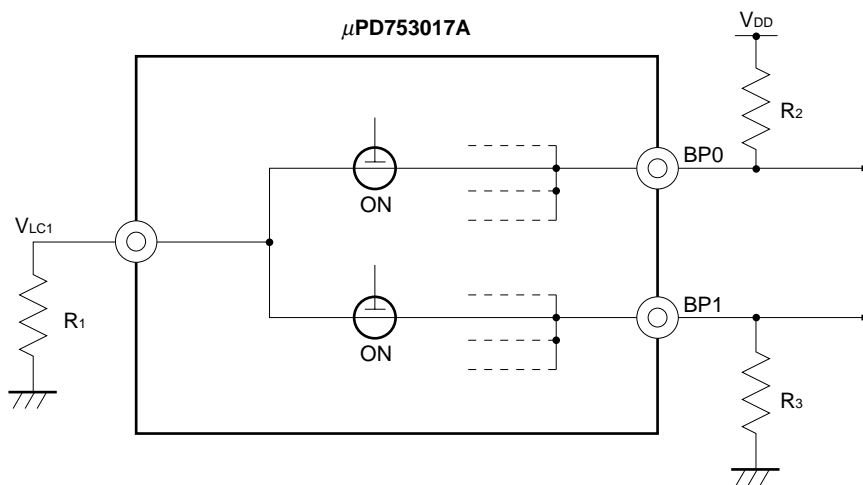
Pin Name	I/O	Alternate Function	Function	8-bit I/O	After Reset	I/O Circuit Type ^{Note 1}
P60	I/O	KR0	Programmable 4-bit input/output port (PORT6). This port can be specified for input/output bit-wise. Connection of on-chip pull-up resistors can be specified by software in 4-bit units.	Yes	Input	<F>-A
P61		KR1				
P62		KR2				
P63		KR3				
P70	I/O	KR4	4-bit input/output port (PORT7). Connection of on-chip pull-up resistors can be specified by software in 4-bit units.		Input	<F>-A
P71		KR5				
P72		KR6				
P73		KR7				
BP0	Output	S24	1-bit output port (BIT PORT). Also used for segment output pins.	No	Note 2	H-A
BP1		S25				
BP2		S26				
BP3		S27				
BP4	Output	S28				
BP5		S29				
BP6		S30				
BP7		S31				

Notes 1. Circuit types enclosed in brackets indicate the Schmitt trigger input.

2. BP0 through BP7 select V_{LC1} as an input source.

However, the output levels change depending on the external circuit of BP0 through BP7 and V_{LC1} .

Example Because BP0 through BP7 are mutually connected inside the μPD753017A, the output levels of BP0 through BP7 are determined by R_1 , R_2 , and R_3 .



3.2 Non-port Pins (1/2)

Pin Name	I/O	Alternate Function	Function	After Reset	I/O Circuit Type ^{Note 1}
TI0	Input	P13	Inputs external event pulses to the timer/event counter.	Input	-C
TI1		P12/INT2			
TI2					
PTO0	Output	P20	Timer/event counter output	Input	E-B
PTO1		P21			
PTO2		P22/PCL			
PCL		P22/PTO2	Clock output		
BUZ		P23	Optional frequency output (for buzzer output or system clock trimming)		
SCK	I/O	P01	Serial clock input/output	Input	<F>-A
SO/SB0		P02	Serial data output Serial data bus input/output		<F>-B
SI/SB1		P03	Serial data input Serial data bus input/output		<M>-C
INT4	Input	P00	Edge detection vectored interrupt input (both rising edge and falling edge detection)	Input	
INT0	Input	P10	Edge detection vectored interrupt input (detection edge can be selected) INT0/P10 can select noise elimination circuit.	Input	-C
INT1		P11			
INT2	Input	P12/TI1/TI2	Rising edge detection testable input	Input	-C
KR0-KR3	Input	P60-P63	Falling edge detection testable input	Input	<F>-A
KR4-KR7	Input	P70-P73	Falling edge detection testable input	Input	<F>-A
S0-S23	Output	–	Segment signal output	Note 2	G-A
S24-S31	Output	BP0-BP7	Segment signal output	Note 2	H-A
COM0-COM3	Output	–	Common signal output	Note 2	G-B
V _{LC0} -V _{LC2}	–	–	LCD drive power On-chip split resistor is enable (mask option).	–	–
BIAS	Output	–	Output for external split resistor disconnect	Note 3	–
LCDCL ^{Note 4}	Output	P30	Clock output for externally expanded driver	Input	E-B
SYNC ^{Note 4}	Output	P31	Clock output for externally expanded driver synchronization	Input	E-B

- Notes**
1. Circuit types enclosed in brackets indicate the Schmitt trigger input.
 2. Each display output selects the following V_{LCx} as input source.
S0-S31: V_{LC1}, COM0-COM2: V_{LC2}, COM3: V_{LC0}
 3. When a split resistor is contained Low level
When no split resistor is contained High impedance
 4. These pins are provided for future system expansion. At present, these pins are used only as pins P30 and P31.

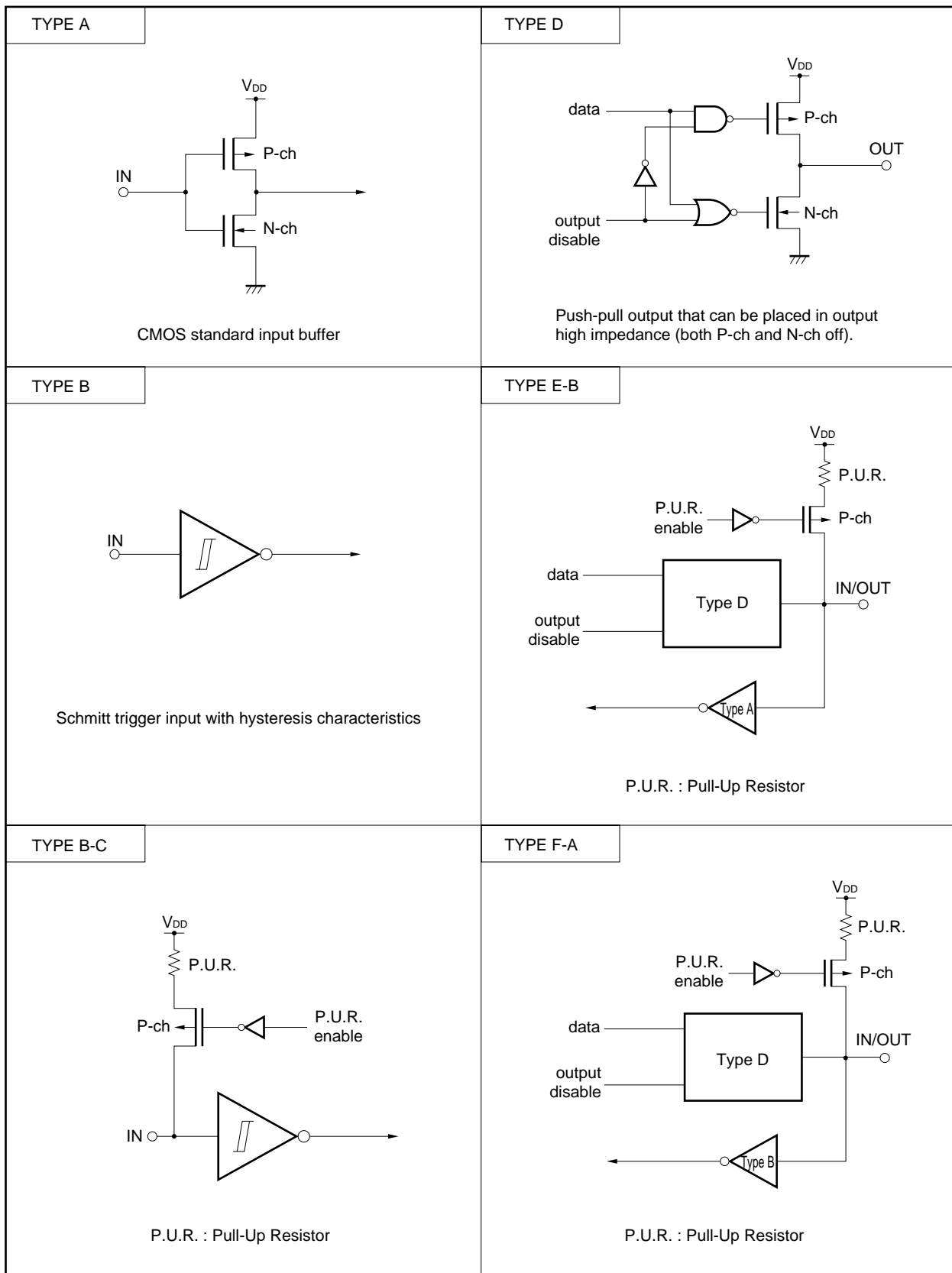
3.2 Non-port Pins (2/2)

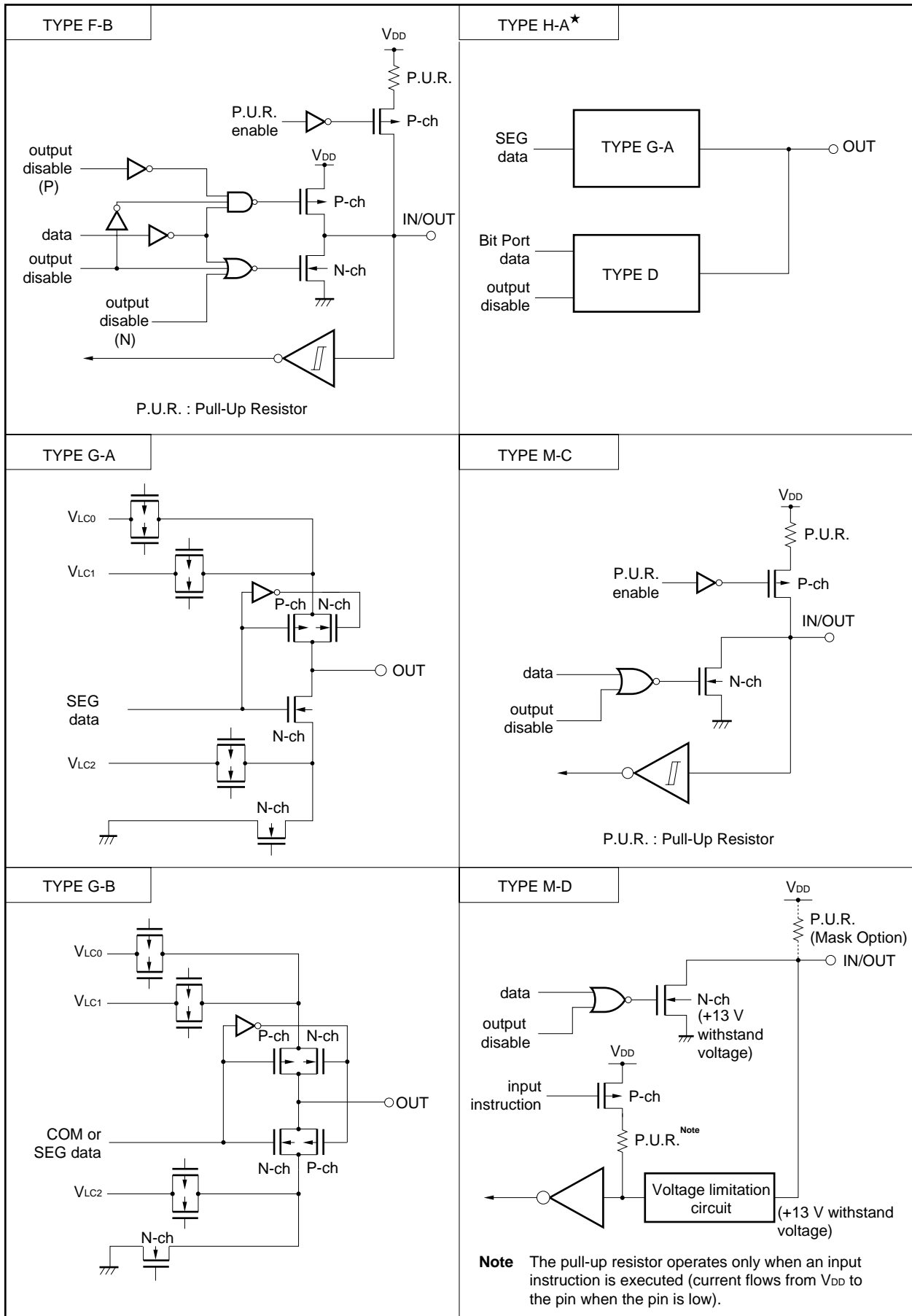
Pin Name	I/O	Alternate Function	Function	After Reset	I/O Circuit Type ^{Note}
X1	Input	–	Crystal/ceramic connection pin for the mainsystem clock oscillation. When inputting the external clock, input the external clock to pin X1, and the inverted phase of the external clock to pin X2.	–	–
X2	–	–			
XT1	Input	–	Crystal connection pin for the subsystem clock oscillation. When the external clock is used, input the external clock to pin XT1, and the inverted phase of the external clock to pin XT2. Pin XT1 can be used as a 1-bit input (test) pin.	–	–
XT2	–				
$\overline{\text{RESET}}$	Input	–	System reset input (low level active)	–	
IC	–	–	Internally connected. Connect directly to V _{DD} .	–	–
V _{DD}	–	–	Positive power supply	–	–
V _{SS}	–	–	GND	–	–

Note Circuit types enclosed in brackets indicate the Schmitt trigger input.

3.3 Pin Input/Output Circuits

The μPD753017A pin input/output circuits are shown schematically.





3.4 Recommended Connection for Unused Pins

Table 3-1. List of Recommended Connection for Unused Pins

Pin	Recommended Connection	
P00/INT4	Connect to V _{SS} or V _{DD}	
P01/ $\overline{\text{SCK}}$	Connect to V _{SS} or V _{DD} via a resistor individually	
P02/SO/SB0		
P03/SI/SB1	Connect to V _{SS}	
P10/INT0, P11/INT1	Connect to V _{SS} or V _{DD}	
P12/TI1/TI2/INT2		
P13/TI0		
P20/PTO0	Input: Connect to V _{SS} or V _{DD} via a resistor individually Output: Leave open	
P21/PTO1		
P22/PTO2/PCL		
P23/BUZ		
P30/LCDCL		
P31/SYNC		
P32		
P33		
P40-P43		Input: Connect to V _{SS} Output: Connect to V _{SS} (do not connect a pull-up resistor of mask option)
P50-P53		
P60/KR0-P63/KR3	Input: Connect to V _{SS} or V _{DD} via a resistor individually Output: Leave open	
P70/KR4-P73/KR7		
S0-S23	Leave open	
S24/BP0-S31/BP7		
COM0-COM3		
V _{LC0} -V _{LC2}	Connect to V _{SS}	
BIAS	Only if all of V _{LC0} -V _{LC2} are unused, connect to V _{SS} . In other cases, leave open.	
XT1	Connect to V _{SS}	
XT2 ^{Note}	Leave open	
IC	Connect to V _{DD} directly	

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Note When the subsystem clock is not used, set SOS.0 to 1 (so as not to use the internal feedback resistor).

4. SWITCHING FUNCTION BETWEEN Mk I MODE AND Mk II MODE

4.1 Differences between Mk I Mode and Mk II Mode

The CPU of μPD753017A has the following two modes: Mk I and Mk II, either of which can be selected. The mode can be switched by the bit 3 of the stack bank select register (SBS).

- Mk I mode: Upward compatible with μPD75316B.
Can be used in the 75XL CPU with a ROM capacity of up to 16K bytes.
- Mk II mode: Incompatible with μPD75316B.
Can be used in all the 75XL CPU's including those products whose ROM capacity is more than 16K bytes.

Table 4-1. Differences between Mk I Mode and Mk II Mode

	Mk I Mode	Mk II Mode
Program memory (bytes)	<ul style="list-style-type: none"> • μPD753012A : 12288 • μPD753016A, 753017A : 16384 	<ul style="list-style-type: none"> • μPD753012A : 12288 • μPD753016A : 16384 • μPD753017A : 24576
Number of stack bytes for subroutine instructions	2 bytes	3 bytes
BRA !addr1 instruction CALLA !addr1 instruction	Not available	Available
CALL !addr instruction	3 machine cycles	4 machine cycles
CALLF !faddr instruction	2 machine cycles	3 machine cycles

Caution The Mk II mode supports a program area exceeding 16 Kbytes for the 75X and 75XL series. Therefore, this mode is effective for enhancing software compatibility with products exceeding 16 Kbytes.

When the Mk II mode is selected, the number of stack bytes used during execution of subroutine call instructions increases by one byte per stack compared to the Mk I mode. When the CALL !addr and CALLF !faddr instructions are used, the machine cycle becomes longer by one machine cycle. Therefore, use the Mk I mode if the RAM efficiency and processing performance are more important than software compatibility.

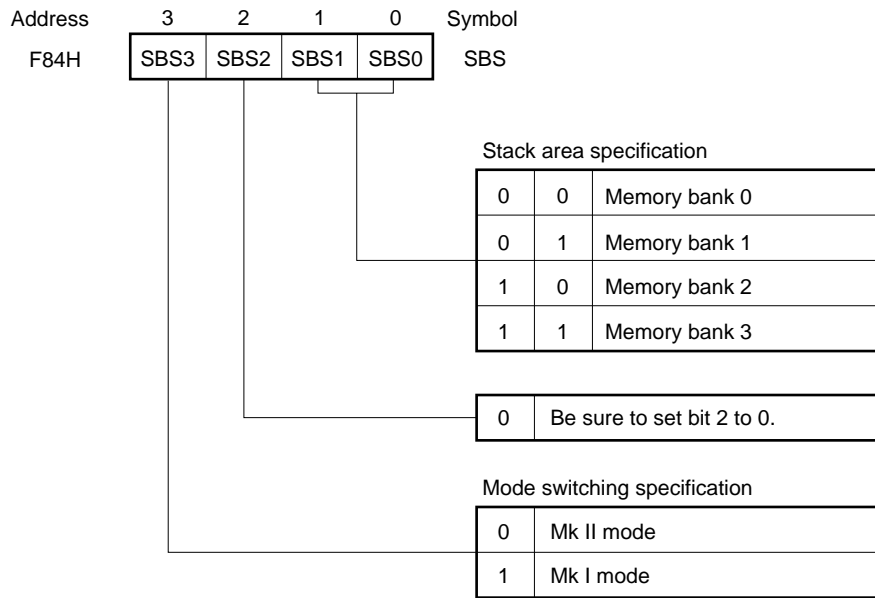
4.2 Setting Method of Stack Bank Select Register (SBS)

Switching between the Mk I mode and Mk II mode can be done by the stack bank select register (SBS). Figure 4-1 shows the format.

The SBS is set by a 4-bit memory manipulation instruction. When using the Mk I mode, the SBS must be initialized to 10XXB^{Note} at the beginning of a program. When using the Mk II mode, it must be initialized to 00XXB^{Note}.

Note Set the desired value in the XX positions.

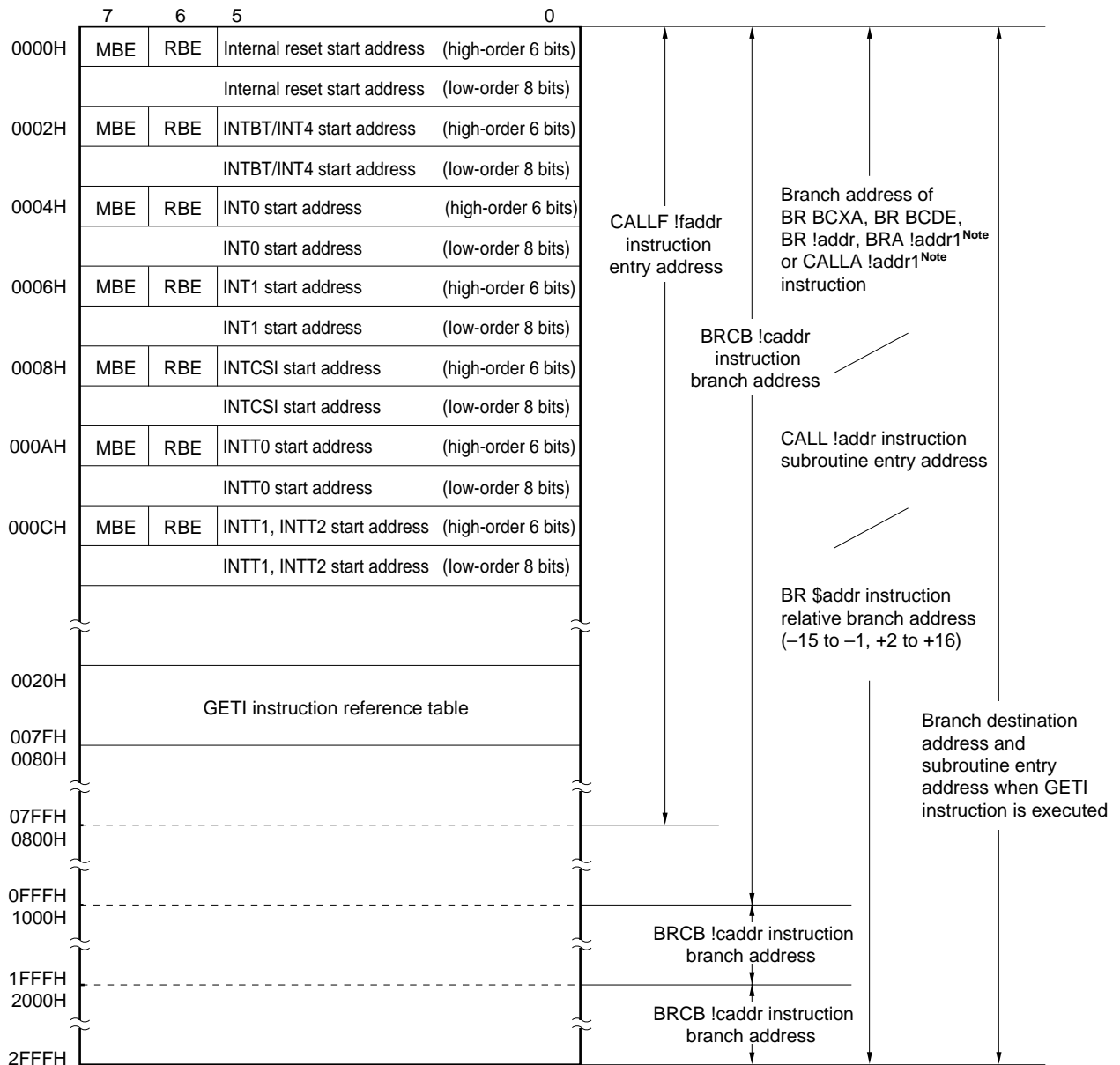
Figure 4-1. Stack Bank Select Register Format



Caution Since SBS. 3 is set to “1” after a RESET signal is generated, the CPU operates in the Mk I mode. When executing an instruction in the Mk II mode, set SBS. 3 to “0” to select the Mk II mode.

Figure 5-1. Program Memory Map (1/3)

(a) μPD753012A

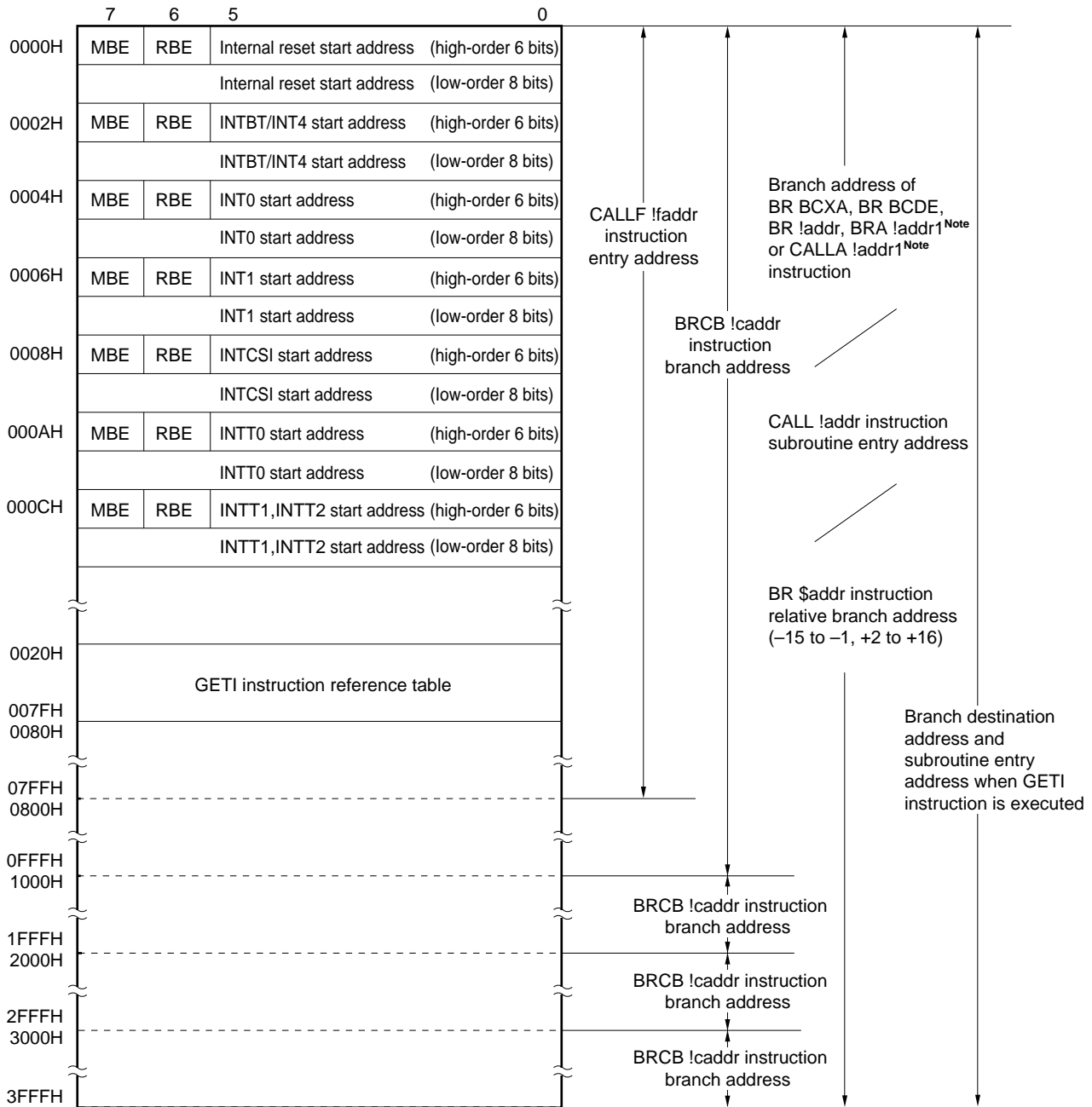


Note Can be used only in the Mk II mode.

Remark In addition to the above, a branch can be taken to the address indicated by changing only the low-order 8 bits of PC by executing the BR PCDE, BR PCXA instruction.

Figure 5-1. Program Memory Map (2/3)

(b) μPD753016A

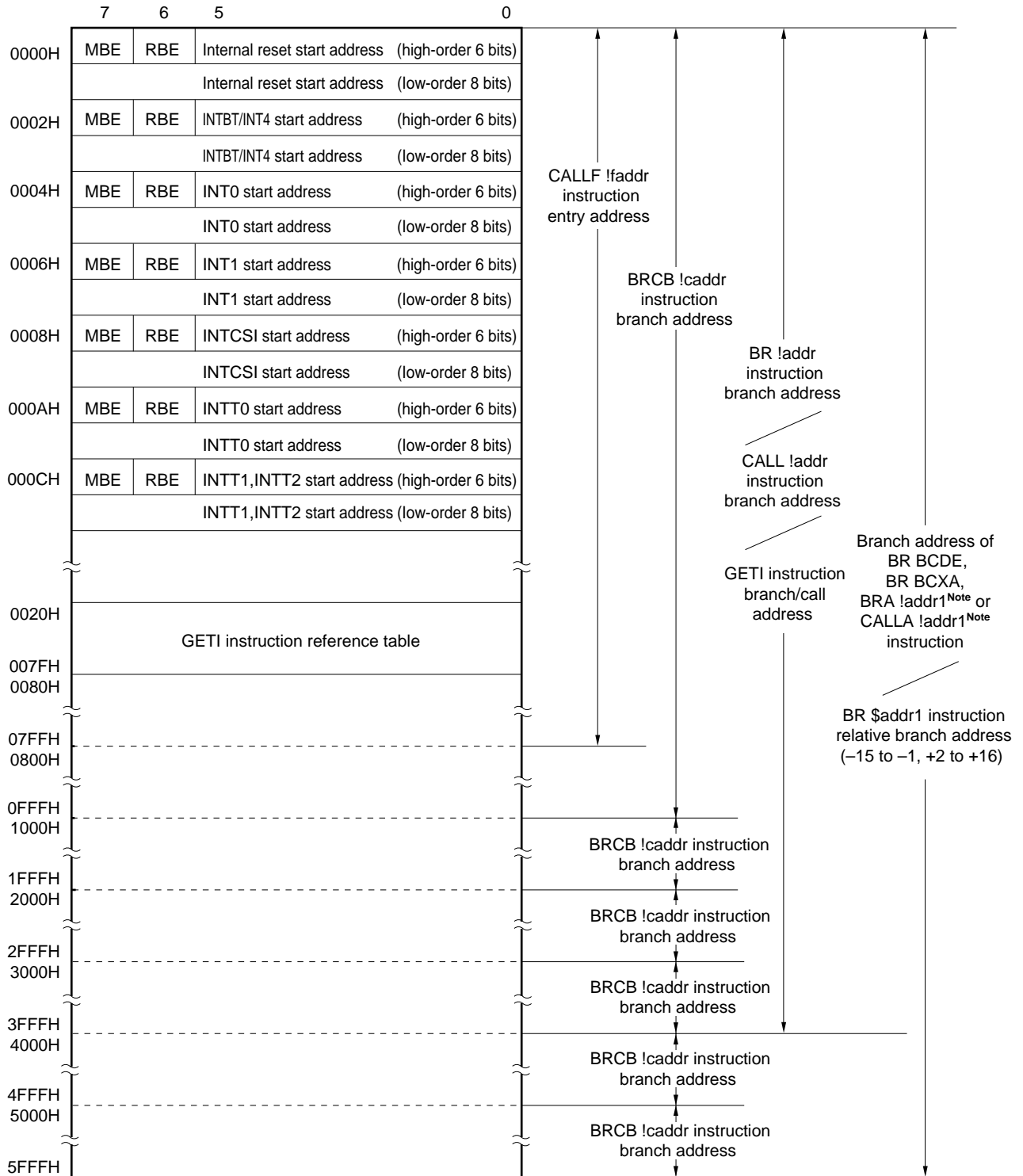


Note Can be used only in the Mk II mode.

Remark In addition to the above, a branch can be taken to the address indicated by changing only the low-order 8 bits of PC by executing the BR PCDE, BR PCXA instruction.

Figure 5-1. Program Memory Map (3/3)

(c) μPD753017A

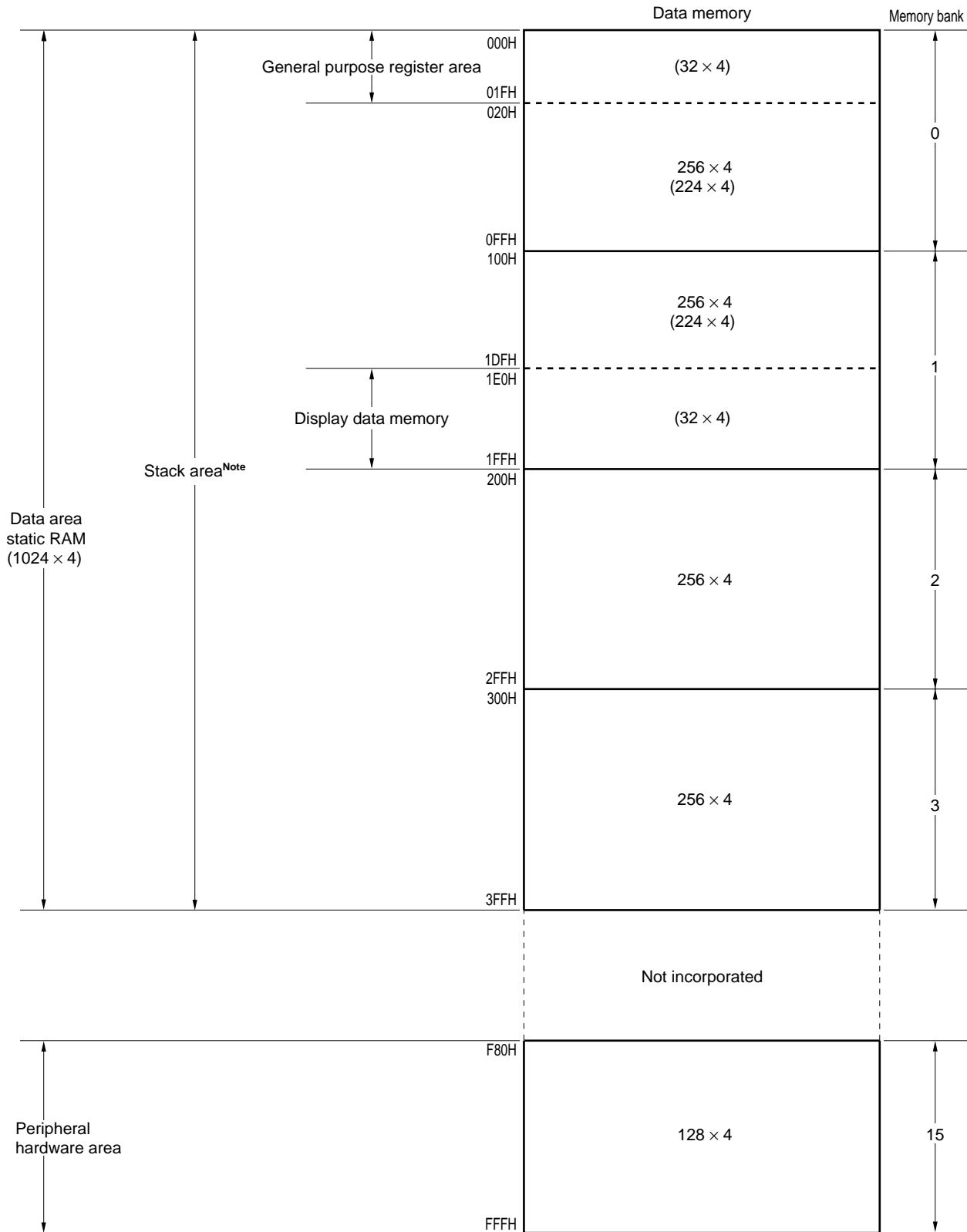


Note Can be used only in the Mk II mode.

Caution The interrupt vector start address shown above consists of 14 bits. Set it in 16K space (0000H-3FFFH).

Remark In addition to the above, a branch can be taken to the address indicated by changing only the low-order 8 bits of PC by executing the BR PCDE, BR PCXA instruction.

Figure 5-2. Data Memory Map



Note For stack area, one memory bank can be selected among memory banks 0 to 3.

6. PERIPHERAL HARDWARE FUNCTIONS

6.1 Digital Input/Output Ports

There are four types of I/O ports as follows.

· CMOS input (PORT0, 1)	: 8
· CMOS input/output (PORT2, 3, 6, 7)	: 16
· N-channel open-drain input/output (PORT4, 5)	: 8
· Bit port output (BP0-BP7)	: 8
Total	40

Table 6-1. Types and Features of Digital Ports

Port (Pin Name)	Function	Operation and Features		Remarks
PORT0 (P00-P03)	4-bit input	When the serial interface function is used, the alternate function pins function as output ports depending on the operation mode.		Also used for the INT4, SCK, SO/SB0, SI/SB1 pins.
PORT1 (P10-P13)		Input-only port		Also used for the INT0-INT2 and T10-T12 pins.
PORT2 (P20-P23)	4-bit I/O	Can be set to input mode or output mode in 4-bit units.		Also used for the PTO0-PTO2, PCL, BUZ pins.
PORT3 (P30-P33)		Can be set to input mode or output mode in 1/4-bit units.		Also used for the LCDCL, SYNC pins.
PORT4 (P40-P43)	4-bit I/O (N-channel open-drain, 13 V withstanding)	Can be set to input mode or output mode in 4-bit units.	Ports 4 and 5 are paired and data can be input/output in 8-bit units.	On-chip pull-up resistor can be specified bit-wise by mask option.
PORT5 (P50-P53)				
PORT6 (P60-P63)	4-bit I/O	Can be set to input mode or output mode in 1/4-bit units.	Ports 6 and 7 are paired and data can be input/output in 8-bit units.	Also used for the KR0-KR3 pins.
PORT7 (P70-P73)		Can be set to input mode or output mode in 4-bit units.		Also used for the KR4-KR7 pins.
BP0-BP7	1-bit output	Outputs data bit-wise. Can be switched to LCD drive segment output S24-S31 by software.		—

6.2 Clock Generator

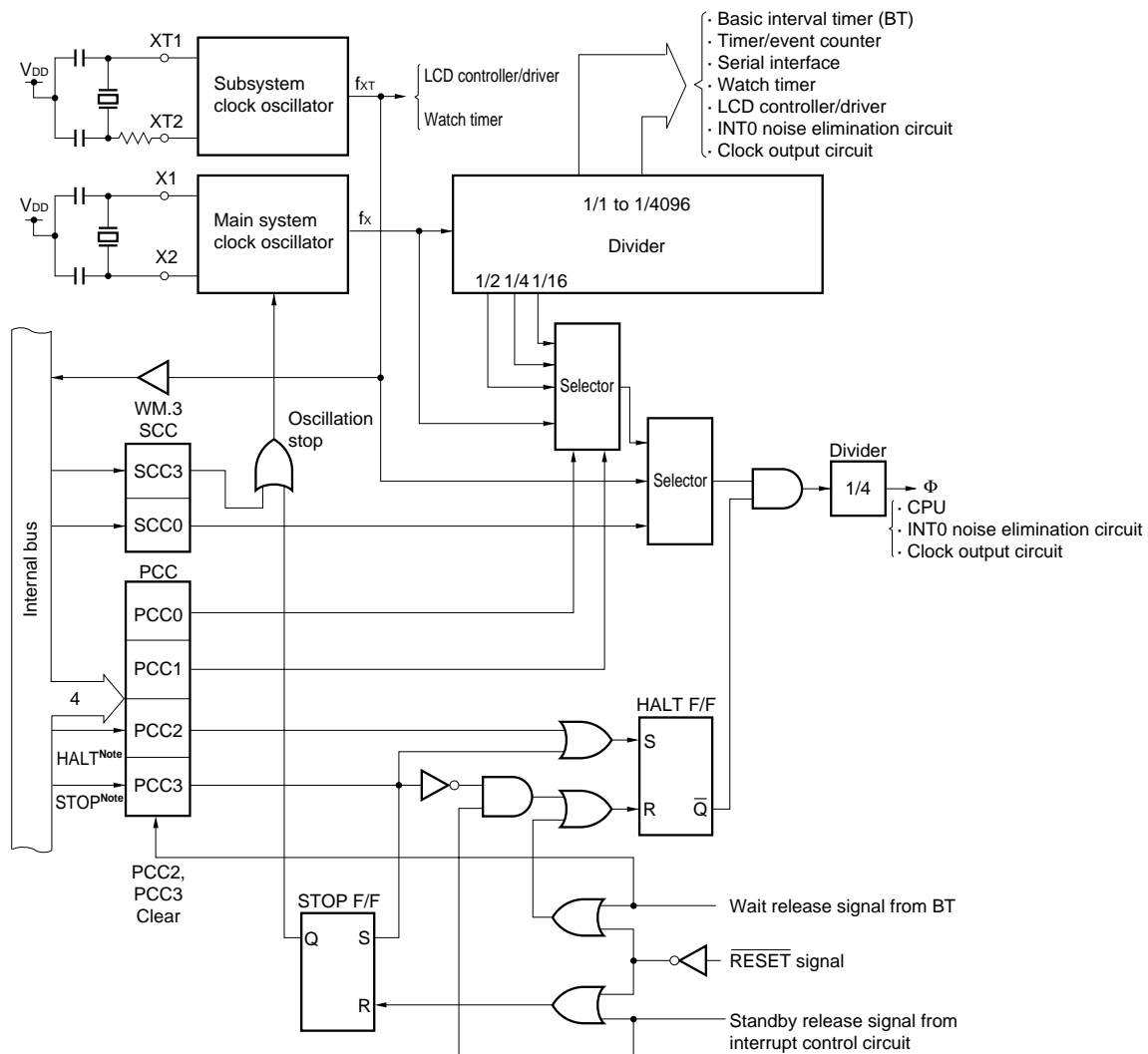
Operation of the clock generator is determined by the processor clock control register (PCC) and system clock control register (SCC).

The two clocks, the main system clock and subsystem clock, are available.

The instruction execution time can be altered.

- 0.95 μ s, 1.91 μ s, 3.81 μ s, 15.3 μ s (main system clock : at 4.19 MHz operation)
- 0.67 μ s, 1.33 μ s, 2.67 μ s, 10.7 μ s (main system clock : at 6.0 MHz operation)
- 122 μ s (subsystem clock : at 32.768 kHz operation)

Figure 6-1. Clock Generator Block Diagram



Note Instruction execution

- Remarks**
1. f_x = Main system clock frequency
 2. f_{XT} = Subsystem clock frequency
 3. Φ = CPU clock
 4. PCC: Processor Clock Control Register
 5. SCC: System Clock Control Register
 6. One clock cycle (t_{CY}) of Φ equal to one machine cycle of the instruction.

6.3 Subsystem Clock Oscillator Control Functions

The μPD753017A subsystem clock oscillator has the following two control functions.

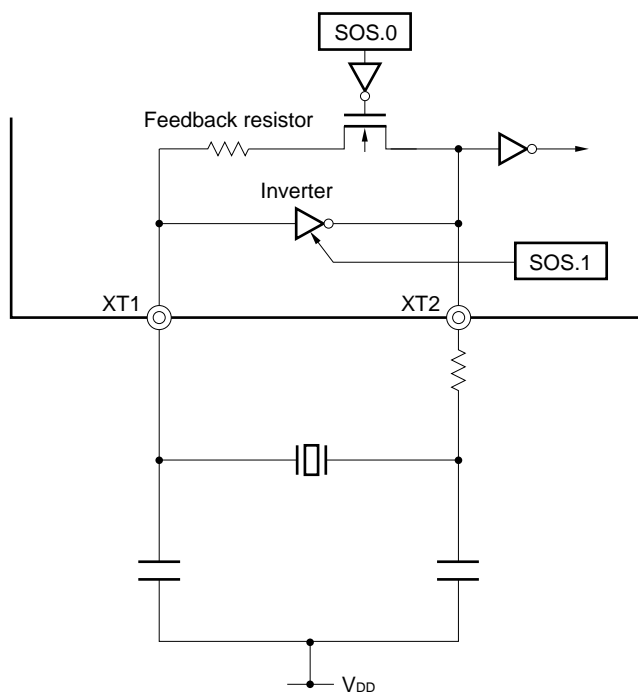
- Selects by software whether an internal feedback resistor is to be used or not^{Note}.
- Reduces current consumption by decreasing the drive current of the on-chip inverter when the supply voltage is high ($V_{DD} \geq 2.7$ V).

Note When the subsystem clock is not used, set SOS.0 to 1 (so as not to use the internal feedback resistor) by software, connect XT1 to V_{SS} , and open XT2. This makes it possible to reduce the current consumption in the subsystem clock oscillator.

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The above functions can be used by switching the bits 0 and 1 of the sub-oscillator control register (SOS). (See Figure 6-2.)

Figure 6-2. Subsystem Clock Oscillator

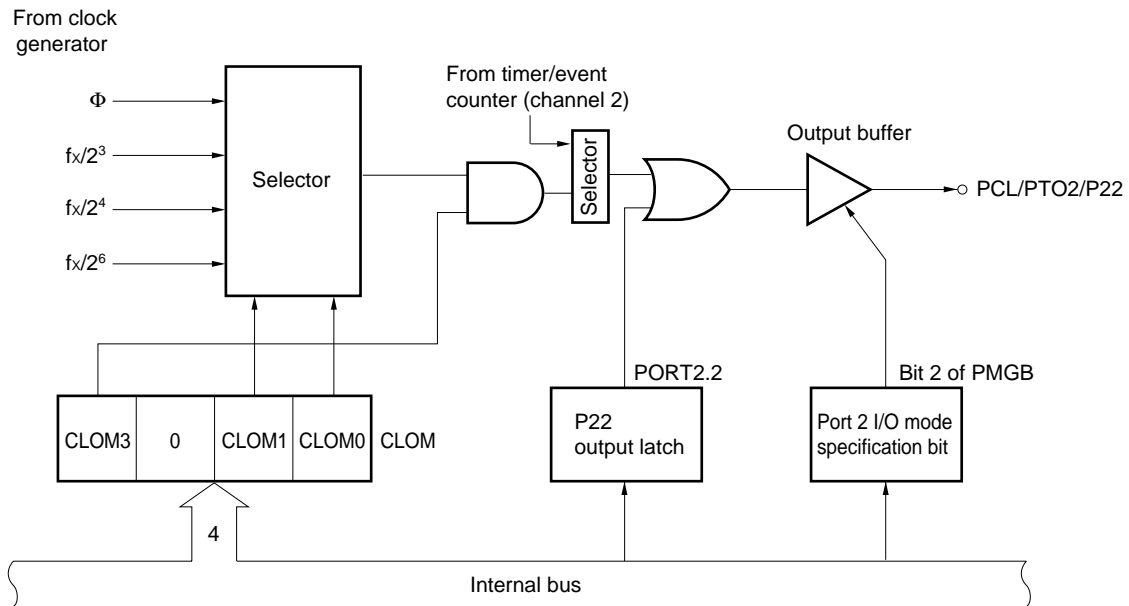


6.4 Clock Output Circuit

The clock output circuit is provided to output the clock pulses from the P22/PTO2/PCL pin to the application of remote control wave outputs and peripheral LSI's.

- Clock output (PCL) : Φ , 524, 262, 65.5 kHz (at 4.19 MHz operation)
 Φ , 750, 375, 93.8 kHz (at 6.0 MHz operation)

Figure 6-3. Clock Output Circuit Block Diagram



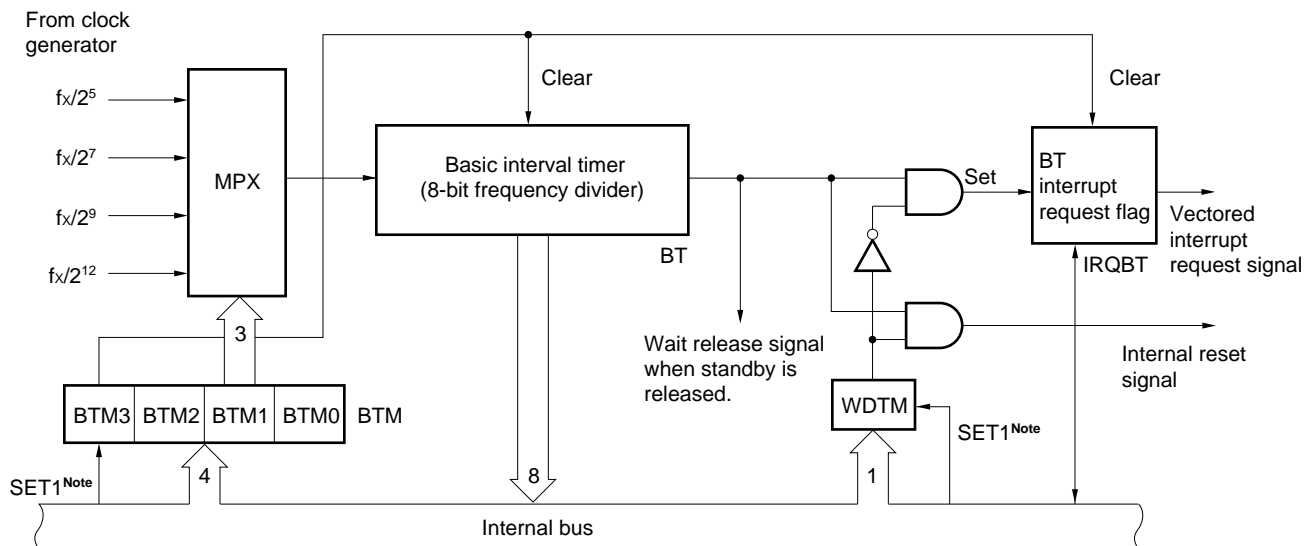
Remark Special care has been taken in designing the chip so that small-width pulses may not be output when switching clock output enable/disable.

6.5 Basic Interval Timer/Watchdog Timer

The basic interval timer/watchdog timer has the following functions.

- Interval timer operation to generate a reference time interrupt
- Watchdog timer operation to detect a runaway of program and reset the CPU
- Selects and counts the wait time when the standby mode is released
- Reads the contents of counting

Figure 6-4. Basic Interval Timer/Watchdog Timer Block Diagram



Note Instruction execution

6.7 Timer/Event Counter

The μPD753017A has three channels of timer/event counter. The timer/event counter has the following functions.

- Programmable interval timer operation
- Square wave output of any frequency to the PTO_n pin (n = 0, 1)
- Event counter operation
- Divides the frequency of signal input via the TIn pin to 1-Nth of the original signal and outputs the divided frequency to the PTO_n pin (frequency division operation).
- Supplies the shift clock to the serial interface circuit (channel 0 only).
- Calls the count value.

The timer/event counter operates in the following four modes as set by the mode register.

Table 6-2. Operation Modes of Timer/Event Counter

Mode	Channel	Channel 0	Channel 1	Channel 2
	8-bit timer/event counter mode		Yes	Yes
	Gate control function	No ^{Note}	No	Yes
PWM pulse generator mode		No	No	Yes
16-bit timer/event counter mode		No	Yes	
	Gate control function	No ^{Note}	Yes	
Carrier generator mode		No	Yes	

Note Used for gate control signal generation

Figure 6-6. Timer/Event Counter Block Diagram (Channel 0)

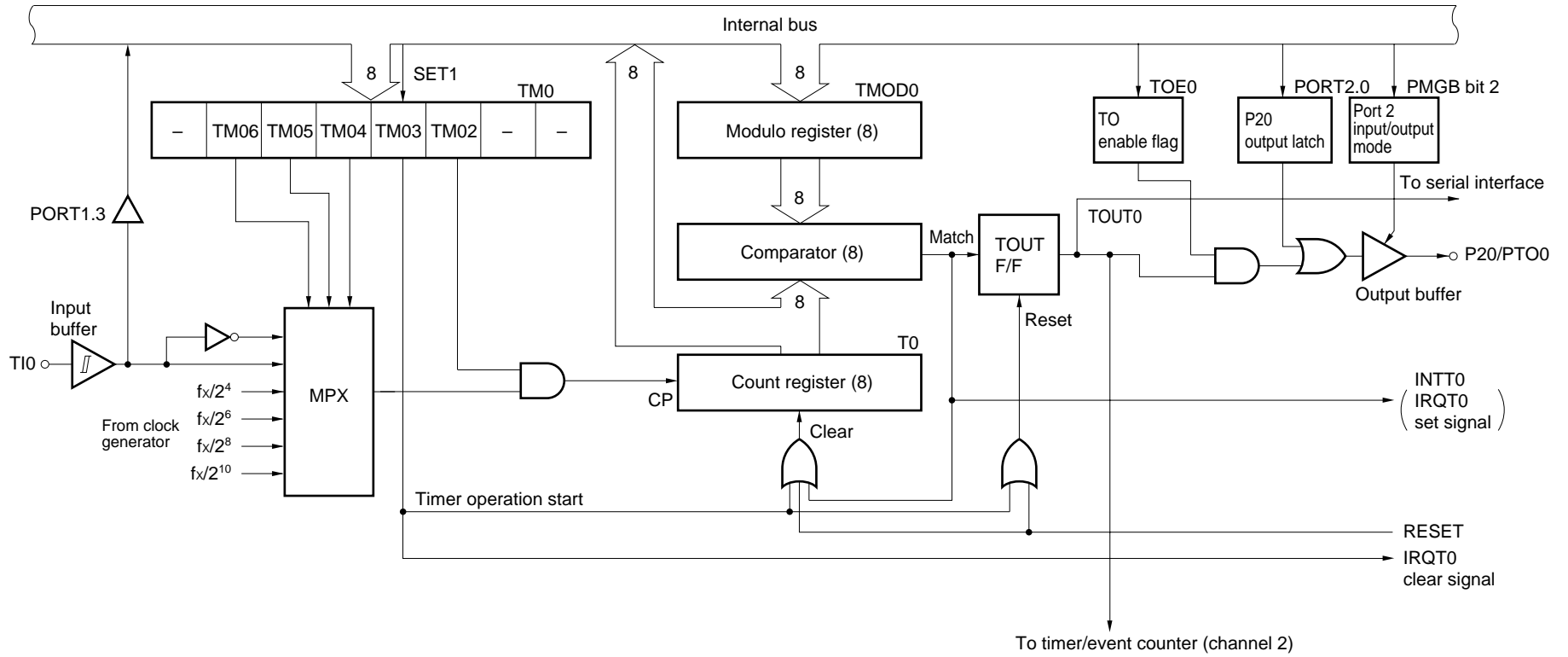


Figure 6-7. Timer/Event Counter Block Diagram (Channel 1)

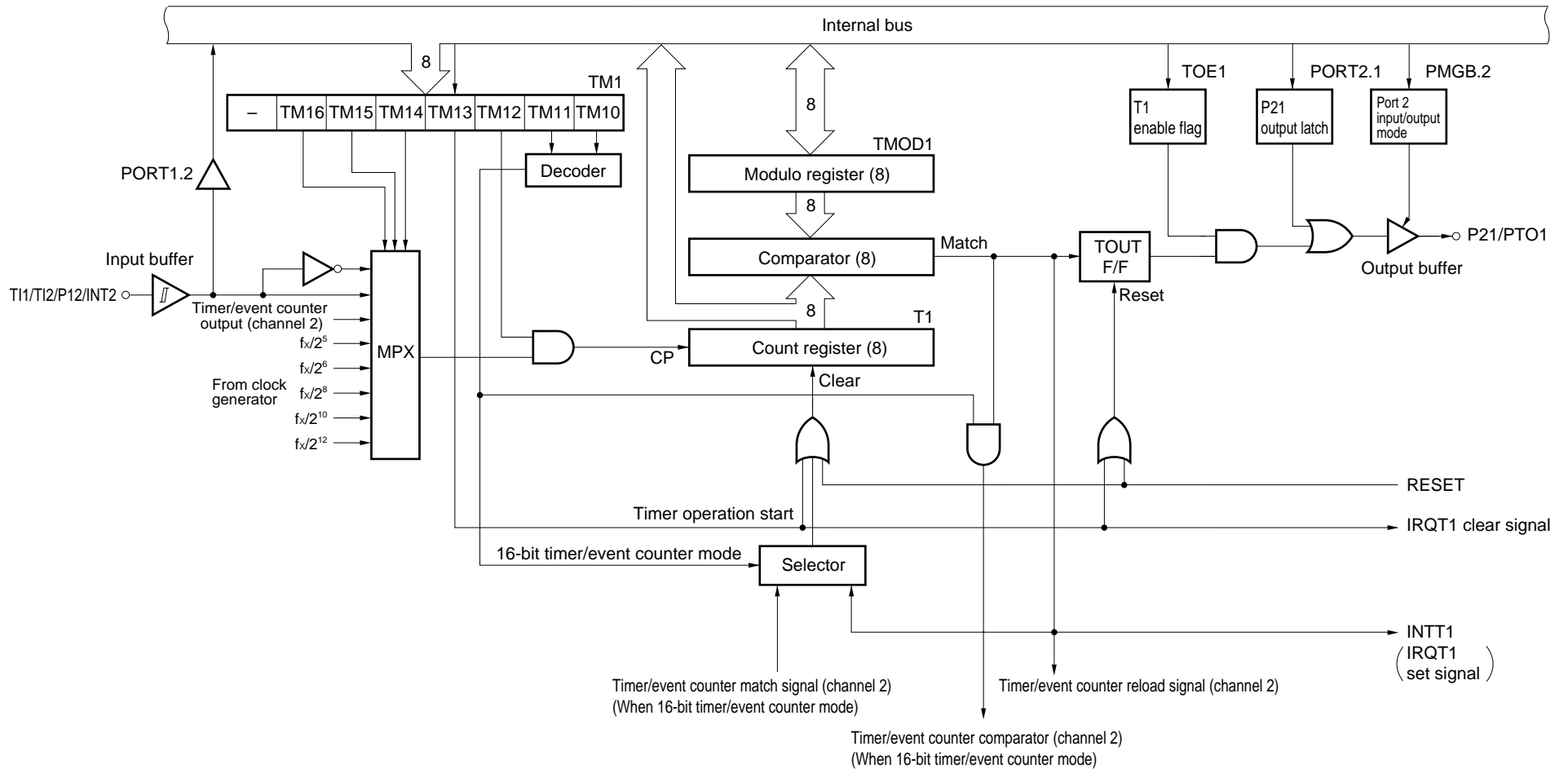
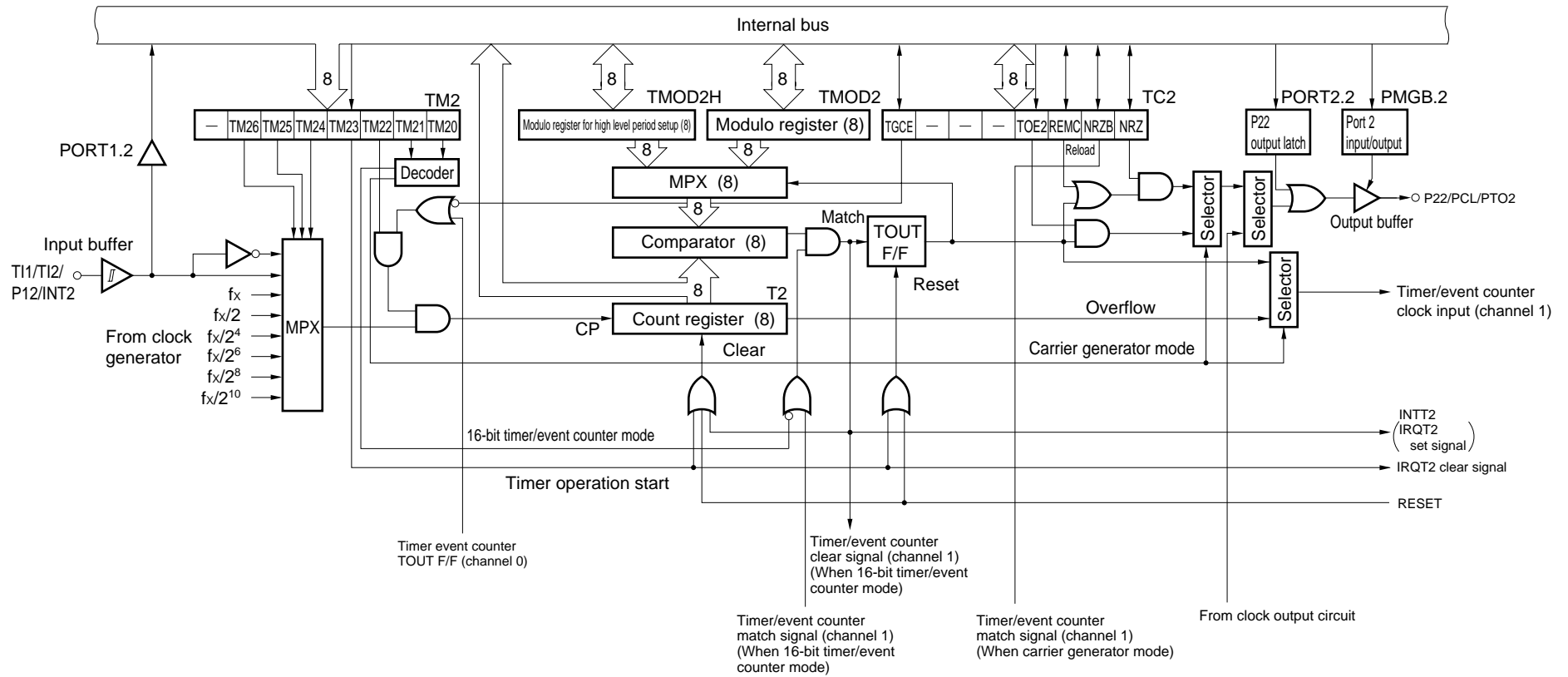


Figure 6-8. Timer/Event Counter Block Diagram (Channel 2)*

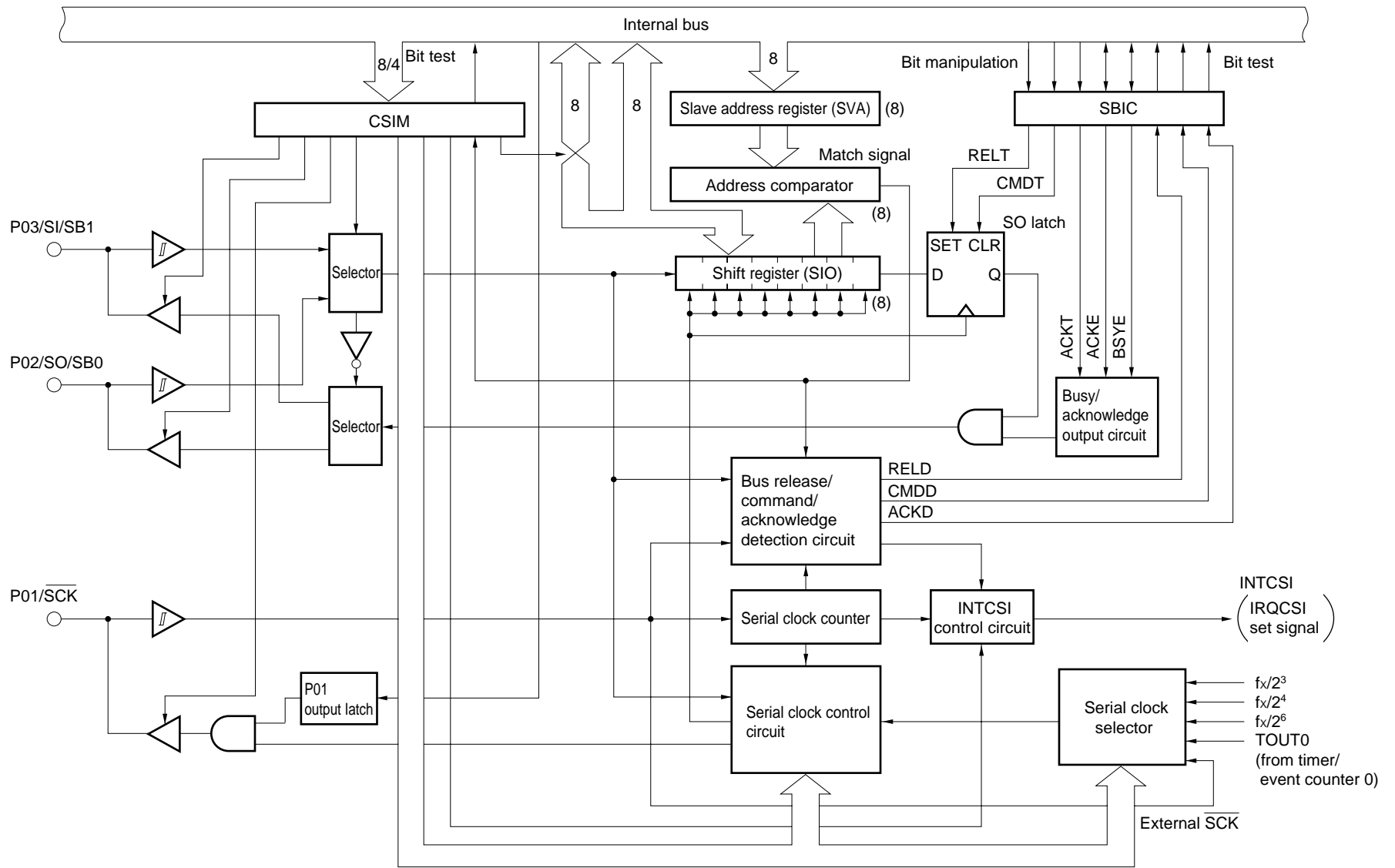


6.8 Serial Interface

The μ PD753017A is provided with an 8-bit clocked serial interface. This serial interface operates in the following four modes:

- Operation stop mode
- 3-wire serial I/O mode
- 2-wire serial I/O mode
- SBI mode

Figure 6-9. Serial Interface Block Diagram



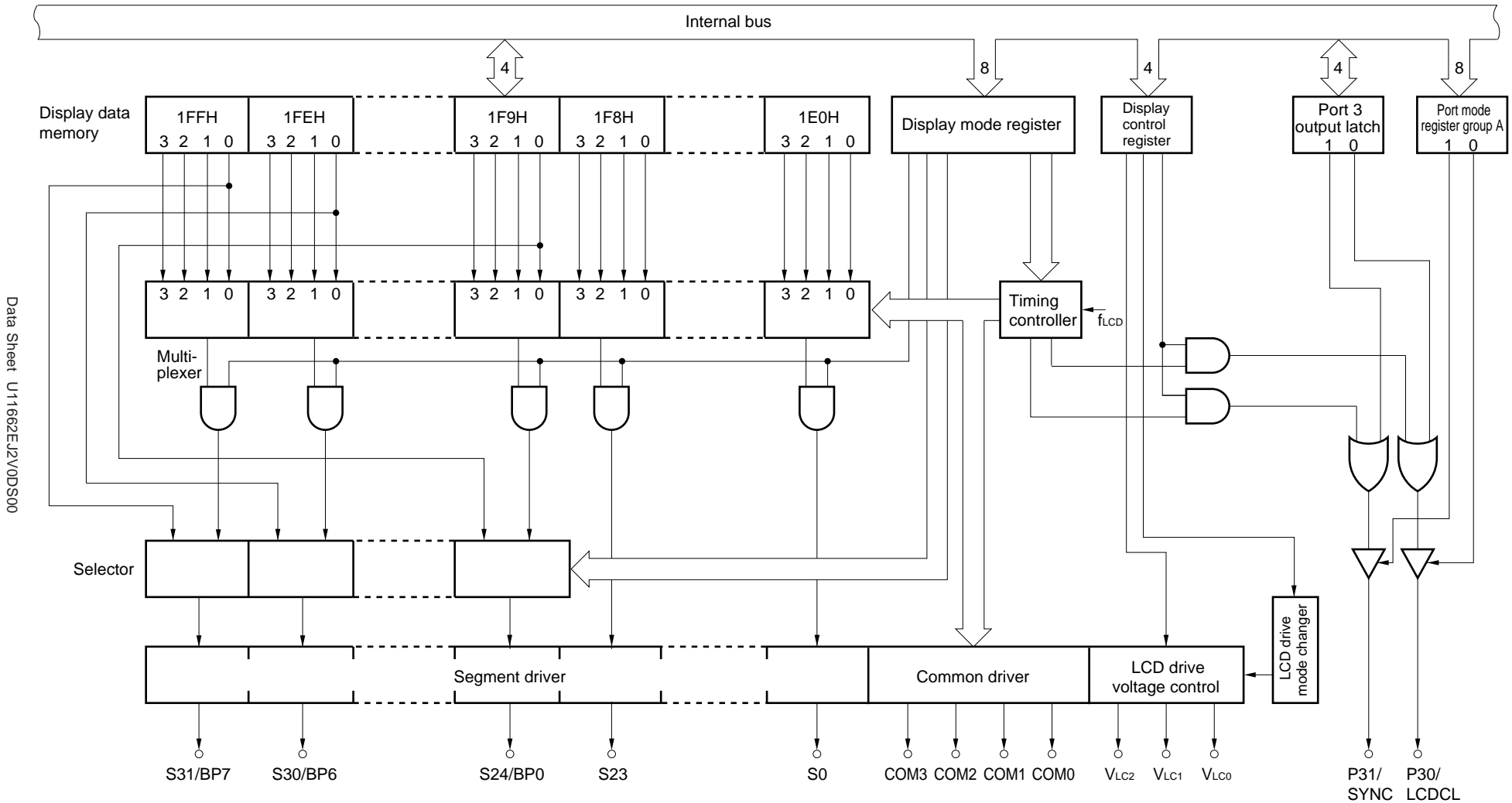
6.9 LCD Controller/Driver

The μ PD753017A incorporates a display controller which generates segment and common signals according to the display data memory contents and incorporates segment and common drivers which can drive the LCD panel directly.

The μ PD753017A LCD controller/driver functions are as follows:

- Display data memory is read automatically by DMA operation and segment and common signals are generated.
- Display mode can be selected from among the following five:
 - 〈1〉 Static
 - 〈2〉 1/2 duty (time multiplexing by 2), 1/2 bias
 - 〈3〉 1/3 duty (time multiplexing by 3), 1/2 bias
 - 〈4〉 1/3 duty (time multiplexing by 3), 1/3 bias
 - 〈5〉 1/4 duty (time multiplexing by 4), 1/3 bias
- A frame frequency can be selected from among four in each display mode.
- A maximum of 32 segment signal output pins (S0-S31) and four common signal output pins (COM0-COM3).
- The segment signal output pins (S24-S27 and S28-S31) can be changed to the output ports in 4-pin units.
- Split-resistor can be incorporated to supply LCD drive power (mask option).
 - Various bias methods and LCD drive voltages can be applicable.
 - When display is off, current flow to the split resistor is cut.
- Display data memory not used for display can be used for normal data memory.
- It can also operate by using the subsystem clock.

Figure 6-10. LCD Controller/Driver Block Diagram

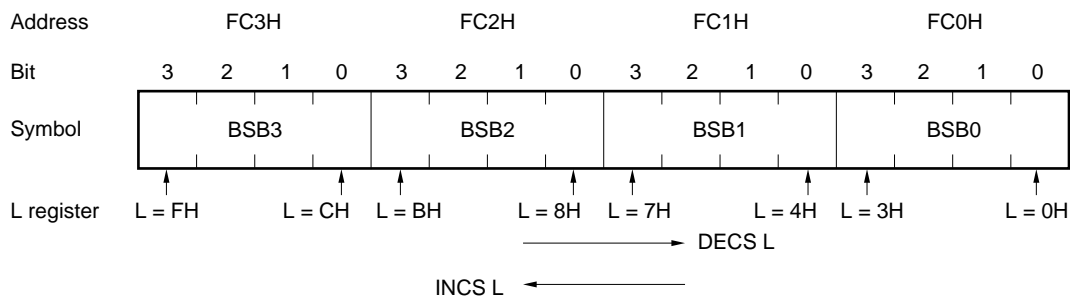


Data Sheet U11662EJ2V0DS00

6.10 Bit Sequential Buffer ... 16 Bits

The bit sequential buffer (BSB) is a special data memory for bit manipulation and the bit manipulation can be easily performed by changing the address specification and bit specification in sequence, therefore it is useful when processing a long data bit-wise.

Figure 6-11. Bit Sequential Buffer Format



- Remarks**
1. In the pmem.@L addressing, the specified bit moves corresponding to the L register.
 2. In the pmem.@L addressing, the BSB can be manipulated regardless of MBE/MBS specification.

7. INTERRUPT FUNCTION AND TEST FUNCTION

μ PD753017A has eight types of interrupt sources and two types of test sources. Among the test sources, INT2 is provided with two testable inputs for edge detection.

μ PD753017A has the following functions in the interrupt control circuit.

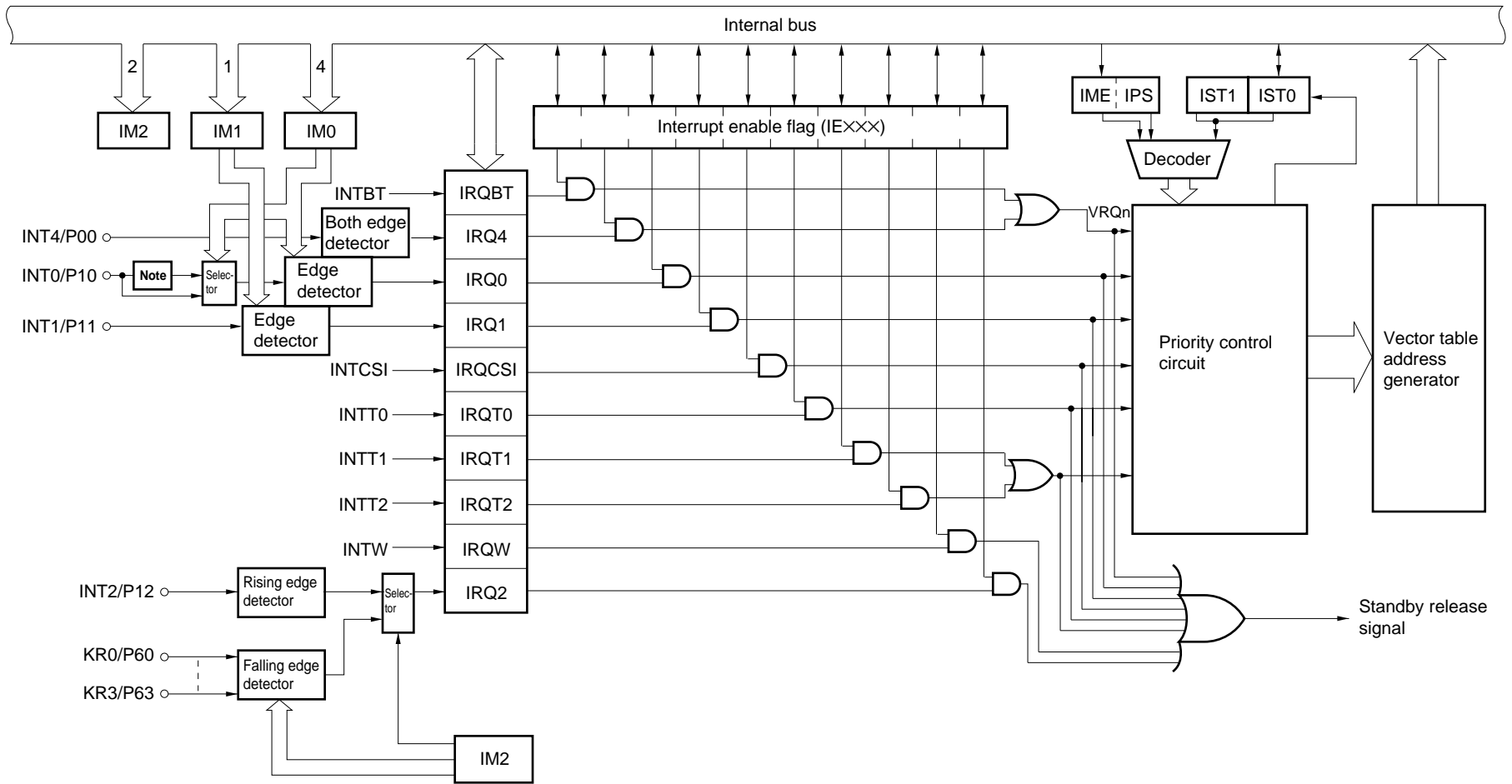
(1) Interrupt function

- Vectored interrupt function for hardware control, enabling/disabling the interrupt acceptance by the interrupt enable flag (IEXXX) and interrupt master enable flag (IME).
- Can set any interrupt start address.
- Nesting interrupts wherein the order of priority can be specified by the interrupt priority select register (IPS).
- Test function of interrupt request flag (IRQXXX). An interrupt generated can be checked by software.
- Release the standby mode. A release interrupt can be selected by the interrupt enable flag.

(2) Test function

- Test request flag (IRQXXX) generation can be checked by software.
- Release the standby mode. The test source to be released can be selected by the test enable flag.

Figure 7-1. Interrupt Control Circuit Block Diagram



Note Noise elimination circuit (Standby release is disabled when noise elimination circuit is selected.)

8. STANDBY FUNCTION

In order to save power consumption while a program is in a standby mode, two types of standby modes (STOP mode and HALT mode) are provided for the μPD753017A.

Table 8-1. Operation Status in Standby Mode

		STOP Mode	HALT Mode
Set instruction		STOP instruction	HALT instruction
System clock when set		Settable only when the main system clock is used.	Settable both by the main system clock and subsystem clock.
Operation status	Clock generator	Only the main system clock stops oscillation.	Only the CPU clock Φ halts (oscillation continues).
	Basic interval timer/watchdog timer	Operation stops	Operation. (The IRQBT is set in the reference interval.) ^{Note 1}
	Serial interface	Operable only when an external \overline{SCK} input is selected as the serial clock.	Operable ^{Note 1}
	Timer/event counter	Operable only when a signal input to the T10-T12 pins is specified as the count clock.	Operable ^{Note 1}
	Watch timer	Operable when f_{XT} is selected as the count clock.	Operable
	LCD controller/driver	Operable only when f_{XT} is selected as the LCDCL.	Operable
	External interrupt	The INT1, 2, and 4 are operable. Only the INT0 is not operated. ^{Note 2}	
	CPU	The operation stops.	
★ Release signals	<ul style="list-style-type: none"> • Interrupt request signal sent from the operable hardware enabled by the interrupt enable flag. • Test request signal sent from the test source enabled by the test enable flag. • RESET input 		

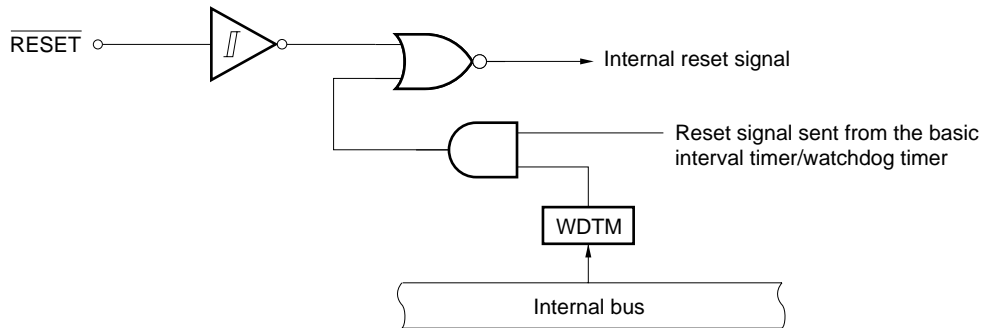
Notes 1. Cannot operate only when the main system clock stops.

2. Can operate only when the noise elimination circuit is not used (IM02 = 1) by bit 2 of the edge detection mode register (IM0).

9. RESET FUNCTION

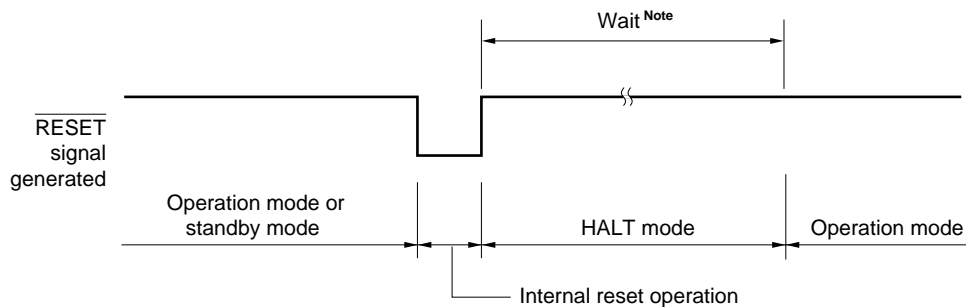
There are two reset inputs: external reset signal ($\overline{\text{RESET}}$) and reset signal sent from the basic interval timer/watchdog timer. When either one of the reset signals are input, an internal reset signal is generated. Figure 9-1 shows the circuit diagram of the above two inputs.

Figure 9-1. Configuration of Reset Function



The μPD753017A is set by the $\overline{\text{RESET}}$ signal generated and each hardware is initialized as listed in Table 9-1. Figure 9-2 shows the timing chart of the reset operation.

Figure 9-2. Reset Operation by $\overline{\text{RESET}}$ Signal Generation



Note The following two times can be selected by the mask option.
 $2^{17}/f_x$ (21.8 ms : at 6.0 MHz operation, 31.3 ms : at 4.19 MHz operation)
 $2^{15}/f_x$ (5.46 ms : at 6.0 MHz operation, 7.81 ms : at 4.19 MHz operation)

Table 9-1. Status of Each Hardware after Reset (1/2)

Hardware		RESET Signal Generation in Standby Mode	RESET Signal Generation in Operation
Program counter (PC)		Sets the low-order 6 bits of program memory's address 0000H to the PC13-PC8 and the contents of address 0001H to the PC7-PC0. Resets the PC14 of the μPD753017A to 0.	Sets the low-order 6 bits of program memory's address 0000H to the PC13-PC8 and the contents of address 0001H to the PC7-PC0. Resets the PC14 of the μPD753017A to 0.
PSW	Carry flag (CY)	Held	Undefined
	Skip flag (SK0-SK2)	0	0
	Interrupt status flag (IST0)	0	0
	Bank enable flag (MBE, RBE)	Sets the bit 6 of program memory's address 0000H to the RBE and bit 7 to the MBE.	Sets the bit 6 of program memory's address 0000H to the RBE and bit 7 to the MBE.
Stack pointer (SP)		Undefined	Undefined
Stack bank select register (SBS)		1000B	1000B
Data memory (RAM)		Held	Undefined
General-purpose register (X, A, H, L, D, E, B, C)		Held	Undefined
Bank select register (MBS, RBS)		0, 0	0, 0
Basic interval timer/ watchdog timer	Counter (BT)	Undefined	Undefined
	Mode register (BTM)	0	0
	Watchdog timer enable flag (WDTM)	0	0
Timer/event counter (T0)	Counter (T0)	0	0
	Modulo register (TMOD0)	FFH	FFH
	Mode register (TM0)	0	0
	TOE0, TOUT F/F	0, 0	0, 0
Timer/event counter (T1)	Counter (T1)	0	0
	Modulo register (TMOD1)	FFH	FFH
	Mode register (TM1)	0	0
	TOE1, TOUT F/F	0, 0	0, 0
Timer/event counter (T2)	Counter (T2)	0	0
	Modulo register (TMOD2)	FFH	FFH
	High level period setting modulo register (TMOD2H)	FFH	FFH
	Mode register (TM2)	0	0
	TOE2, TOUT F/F	0, 0	0, 0
	REMC, NRZ, NRZB	0, 0, 0	0, 0, 0
	TGE	0	0
Watch timer	Mode register (WM)	0	0

Table 9-1. Status of Each Hardware after Reset (2/2)

Hardware		RESET Signal Generation in Standby Mode	RESET Signal Generation in Operation
Serial interface	Shift register (SIO)	Held	Undefined
	Operation mode register (CSIM)	0	0
	SBI control register (SBIC)	0	0
	Slave address register (SVA)	Held	Undefined
Clock generator, clock output circuit	Processor clock control register (PCC)	0	0
	System clock control register (SCC)	0	0
	Clock output mode register (CLOM)	0	0
Sub-oscillator control register (SOS)		0	0
LCD controller/driver	Display mode register (LCDM)	0	0
	Display control register (LCDC)	0	0
Interrupt function	Interrupt request flag (IRQXXX)	Reset (0)	Reset (0)
	Interrupt enable flag (IEXXX)	0	0
	Interrupt master enable flag (IME)	0	0
	INT0, 1, 2 mode registers (IM0, IM1, IM2)	0, 0, 0	0, 0, 0
	Interrupt priority selection register (IPS)	0	0
Digital port	Output buffer	Off	Off
	Output latch	Cleared (0)	Cleared (0)
	I/O mode registers (PMGA, PMGB)	0	0
	Pull-up resistor specification register (POGA)	0	0
Bit sequential buffer (BSB0-BSB3)		Held	Undefined

10. MASK OPTION

The μ PD753017A has the following mask options.

- P40-P43, P50-P53 mask options
On-chip pull-up resistors can be connected.
 - <1> On-chip pull-up resistors are specifiable bit-wise.
 - <2> On-chip pull-up resistors are not specifiable.

- V_{LC0}-V_{LC2} pins, BIAS pin mask option
On-chip split resistor for LCD drive can be connected.
 - <1> Split resistor is not connected.
 - <2> Four 10 k Ω (TYP.) split resistors are connected at the same time.
 - <3> Four 100 k Ω (TYP.) split resistors are connected at the same time.

- Standby function mask option
Wait times can be selected by a $\overline{\text{RESET}}$ signal.
 - <1> $2^{17}/f_x$ (21.8 ms : at $f_x = 6.0$ MHz, 31.3 ms : at $f_x = 4.19$ MHz)
 - <2> $2^{15}/f_x$ (5.46 ms : at $f_x = 6.0$ MHz, 7.81 ms : at $f_x = 4.19$ MHz)

- Subsystem clock mask option
Use of the internal feedback resistor can be selected.
 - <1> Internal feedback resistor can be used.
(Switched ON/OFF via software)
 - <2> Internal feedback resistor cannot be used.
(Switched out in hardware)

11. INSTRUCTION SET

(1) Expression formats and description methods of operands

The operand is described in the operand column of each instruction in accordance with the description method for the operand expression format of the instruction. For details, refer to **RA75X Assembler Package User's Manual—Language (U12385E)**. If there are several elements, one of them is selected.

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Capital letters and the + and – symbols are key words and are described as they are.

For immediate data, appropriate numbers and labels are described.

Instead of the labels such as mem, fmem, pmem, and bit, the symbols of the registers can be described.

However, there are restrictions in the labels that can be described for fmem and pmem. For details, see User's Manual.

Expression Format	Description Method
reg	X, A, B, C, D, E, H, L
reg1	X, B, C, D, E, H, L
rp	XA, BC, DE, HL
rp1	BC, DE, HL
rp2	BC, DE
rp'	XA, BC, DE, HL, XA', BC', DE', HL'
rp'1	BC, DE, HL, XA', BC', DE', HL'
rpa	HL, HL+, HL–, DE, DL
rpa1	DE, DL
n4	4-bit immediate data or label
n8	8-bit immediate data or label
mem	8-bit immediate data or label ^{Note}
bit	2-bit immediate data or label
fmem	FB0H-FBFH, FF0H-FFFH immediate data or label
pmem	FC0H-FFFH immediate data or label
addr	0000H-2FFFH immediate data or label (μPD753012A)
	0000H-3FFFH immediate data or label (μPD753016A, 753017A)
addr1	0000H-5FFFH immediate data or label
caddr	12-bit immediate data or label
faddr	11-bit immediate data or label
taddr	20H-7FH immediate data (where bit0 = 0) or label
PORTn	PORT0-PORT7
IEXXX	IEBT, IET0-IET2, IE0-IE2, IE4, IECSI, IEW
RBn	RB0-RB3
MBn	MB0, MB1, MB2, MB3, MB15

Note mem can be only used even address in 8-bit data processing.

(2) Legend in explanation of operation

A	: A register; 4-bit accumulator
B	: B register
C	: C register
D	: D register
E	: E register
H	: H register
L	: L register
X	: X register
XA	: XA register pair; 8-bit accumulator
BC	: BC register pair
DE	: DE register pair
HL	: HL register pair
XA'	: XA' expanded register pair
BC'	: BC' expanded register pair
DE'	: DE' expanded register pair
HL'	: HL' expanded register pair
PC	: Program counter
SP	: Stack pointer
CY	: Carry flag; bit accumulator
PSW	: Program status word
MBE	: Memory bank enable flag
RBE	: Register bank enable flag
PORT _n	: Port n (n = 0-7)
IME	: Interrupt master enable flag
IPS	: Interrupt priority selection register
IE _{XXX}	: Interrupt enable flag
RBS	: Register bank selection register
MBS	: Memory bank selection register
PCC	: Processor clock control register
.	: Separation between address and bit
(XX)	: The contents addressed by XX
XXH	: Hexadecimal data

(3) Explanation of symbols under addressing area column

*1	MB = MBE•MBS (MBS = 0-3, 15)		Data memory addressing
*2	MB = 0		
*3	MBE = 0 : MB = 0 (000H-07FH) MB = 15 (F80H-FFFFH) MBE = 1 : MB = MBS (MBS = 0-3, 15)		
*4	MB = 15, fmem = FB0H-FBFH, FF0H-FFFFH		
*5	MB = 15, pmem = FC0H-FFFFH		
*6	μPD753012A	addr = 0000H-2FFFH	Program memory addressing
	μPD753016A 753017A	addr = 0000H-3FFFH	
*7	μPD753012A 753016A 753017A (In Mk I mode)	addr = (Current PC) – 15 to (Current PC) – 1 (Current PC) + 2 to (Current PC) + 16	
	μPD753017A (In Mk II mode)	addr1 = (Current PC) – 15 to (Current PC) – 1 (Current PC) + 2 to (Current PC) + 16	
*8	μPD753012A	caddr = 0000H-0FFFH (PC _{13, 12} = 00B) or 1000H-1FFFH (PC _{13, 12} = 01B) or 2000H-2FFFH (PC _{13, 12} = 10B)	
	μPD753016A	caddr = 0000H-0FFFH (PC _{13, 12} = 00B) or 1000H-1FFFH (PC _{13, 12} = 01B) or 2000H-2FFFH (PC _{13, 12} = 10B) or 3000H-3FFFH (PC _{13, 12} = 11B)	
	μPD753017A	caddr = 0000H-0FFFH (PC _{14, 13, 12} = 000B) or 1000H-1FFFH (PC _{14, 13, 12} = 001B) or 2000H-2FFFH (PC _{14, 13, 12} = 010B) or 3000H-3FFFH (PC _{14, 13, 12} = 011B) or 4000H-4FFFH (PC _{14, 13, 12} = 100B) or 5000H-5FFFH (PC _{14, 13, 12} = 101B)	
*9	faddr = 0000H-07FFFH		
*10	taddr = 0020H-007FFFH		
*11	μPD753012A	addr1 = 0000H-2FFFH	
	μPD753016A	addr1 = 0000H-3FFFH	
	μPD753017A	addr1 = 0000H-5FFFH	

- Remarks 1.** MB indicates memory bank that can be accessed.
2. In *2, MB = 0 independently of how MBE and MBS are set.
 3. In *4 and *5, MB = 15 independently of how MBE and MBS are set.
 4. *6 to *11 indicate the areas that can be addressed.

(4) Explanation of number of machine cycles column

S denotes the number of machine cycles required by skip operation when a skip instruction is executed.

The value of S varies as follows.

- When no skip is made: S = 0
- When the skipped instruction is a 1- or 2-byte instruction: S = 1
- When the skipped instruction is a 3-byte instruction^{Note}: S = 2

Note 3-byte instruction: BR !addr, BRA !addr1, CALL !addr or CALLA !addr1 instruction

Caution The GETI instruction is skipped in one machine cycle.

One machine cycle is equal to one cycle of CPU clock Φ (= t_{cy}); time can be selected from among four types by setting PCC.

Instruction Group	Mnemonic	Operand	Number of Bytes	Number of Machine Cycles	Operation	Addressing Area	Skip Condition
Transfer	MOV	A, #n4	1	1	A ← n4		String effect A
		reg1, #n4	2	2	reg1 ← n4		
		XA, #n8	2	2	XA ← n8		String effect A
		HL, #n8	2	2	HL ← n8		String effect B
		rp2, #n8	2	2	rp2 ← n8		
		A, @HL	1	1	A ← (HL)	*1	
		A, @HL+	1	2+S	A ← (HL), then L ← L+1	*1	L = 0
		A, @HL-	1	2+S	A ← (HL), then L ← L-1	*1	L = FH
		A, @rpa1	1	1	A ← (rpa1)	*2	
		XA, @HL	2	2	XA ← (HL)	*1	
		@HL, A	1	1	(HL) ← A	*1	
		@HL, XA	2	2	(HL) ← XA	*1	
		A, mem	2	2	A ← (mem)	*3	
		XA, mem	2	2	XA ← (mem)	*3	
		mem, A	2	2	(mem) ← A	*3	
		mem, XA	2	2	(mem) ← XA	*3	
		A, reg1	2	2	A ← reg1		
		XA, rp'	2	2	XA ← rp'		
		reg1, A	2	2	reg1 ← A		
		rp'1, XA	2	2	rp'1 ← XA		
	XCH	A, @HL	1	1	A ↔ (HL)	*1	
		A, @HL+	1	2+S	A ↔ (HL), then L ← L+1	*1	L = 0
		A, @HL-	1	2+S	A ↔ (HL), then L ← L-1	*1	L = FH
		A, @rpa1	1	1	A ↔ (rpa1)	*2	
		XA, @HL	2	2	XA ↔ (HL)	*1	
		A, mem	2	2	A ↔ (mem)	*3	
		XA, mem	2	2	XA ↔ (mem)	*3	
		A, reg1	1	1	A ↔ reg1		
		XA, rp'	2	2	XA ↔ rp'		

Instruction Group	Mnemonic	Operand	Number of Bytes	Number of Machine Cycles	Operation	Addressing Area	Skip Condition
Table reference	MOVT ^{Note 1}	XA, @PCDE	1	3	XA ← (PC ₁₃₋₈ +DE) _{ROM}		
					● μPD753017A XA ← (PC ₁₄₋₈ +DE) _{ROM}		
		XA, @PCXA	1	3	XA ← (PC ₁₃₋₈ +XA) _{ROM}		
					● μPD753017A XA ← (PC ₁₄₋₈ +XA) _{ROM}		
	XA, @BCDE ^{Note 2}	1	3	XA ← (B _{1,0} +CDE) _{ROM}	*6		
				● μPD753017A XA ← (B ₂₋₀ +CDE) _{ROM}	*11		
	XA, @BCXA ^{Note 2}	1	3	XA ← (B _{1,0} +CXA) _{ROM}	*6		
				● μPD753017A XA ← (B ₂₋₀ +CXA) _{ROM}	*11		
Bit transfer	MOV1	CY, fmem.bit	2	2	CY ← (fmem.bit)	*4	
		CY, pmem.@L	2	2	CY ← (pmem ₇₋₂ +L ₃₋₂ .bit(L ₁₋₀))	*5	
		CY, @H+mem.bit	2	2	CY ← (H+mem ₃₋₀ .bit)	*1	
		fmem.bit, CY	2	2	(fmem.bit) ← CY	*4	
		pmem.@L, CY	2	2	(pmem ₇₋₂ +L ₃₋₂ .bit(L ₁₋₀)) ← CY	*5	
		@H+mem.bit, CY	2	2	(H+mem ₃₋₀ .bit) ← CY	*1	
Operation	ADDS	A, #n4	1	1+S	A ← A+n4		carry
		XA, #n8	2	2+S	XA ← XA+n8		carry
		A, @HL	1	1+S	A ← A+(HL)	*1	carry
		XA, rp'	2	2+S	XA ← XA+rp'		carry
		rp'1, XA	2	2+S	rp'1 ← rp'1+XA		carry
	ADDC	A, @HL	1	1	A, CY ← A+(HL)+CY	*1	
		XA, rp'	2	2	XA, CY ← XA+rp'+CY		
		rp'1, XA	2	2	rp'1, CY ← rp'1+XA+CY		
	SUBS	A, @HL	1	1+S	A ← A-(HL)	*1	borrow
		XA, rp'	2	2+S	XA ← XA-rp'		borrow
		rp'1, XA	2	2+S	rp'1 ← rp'1-XA		borrow
	SUBC	A, @HL	1	1	A, CY ← A-(HL)-CY	*1	
		XA, rp'	2	2	XA, CY ← XA-rp'-CY		
		rp'1, XA	2	2	rp'1, CY ← rp'1-XA-CY		

Notes 1. The above operations in the shaded boxes can be performed only in the Mk II mode. The other operations can be performed only in the Mk I mode.

2. Only the following bits are valid for the B register.

μPD753012A, 753016A : low-order 2 bits

μPD753017A : low-order 3 bits

Remark When the μPD753017A is set in the Mk I mode, PC₁₄ is fixed to 0.

Instruction Group	Mnemonic	Operand	Number of Bytes	Number of Machine Cycles	Operation	Addressing Area	Skip Condition
Operation	AND	A, #n4	2	2	$A \leftarrow A \wedge n4$		
		A, @HL	1	1	$A \leftarrow A \wedge (HL)$	*1	
		XA, rp'	2	2	$XA \leftarrow XA \wedge rp'$		
		rp'1, XA	2	2	$rp'1 \leftarrow rp'1 \wedge XA$		
	OR	A, #n4	2	2	$A \leftarrow A \vee n4$		
		A, @HL	1	1	$A \leftarrow A \vee (HL)$	*1	
		XA, rp'	2	2	$XA \leftarrow XA \vee rp'$		
		rp'1, XA	2	2	$rp'1 \leftarrow rp'1 \vee XA$		
	XOR	A, #n4	2	2	$A \leftarrow A \vee n4$		
		A, @HL	1	1	$A \leftarrow A \vee (HL)$	*1	
		XA, rp'	2	2	$XA \leftarrow XA \vee rp'$		
		rp'1, XA	2	2	$rp'1 \leftarrow rp'1 \vee XA$		
Accumulator manipulation	RORC	A	1	1	$CY \leftarrow A_0, A_3 \leftarrow CY, A_{n-1} \leftarrow A_n$		
	NOT	A	2	2	$A \leftarrow \bar{A}$		
Increment and Decrement	INCS	reg	1	1+S	$reg \leftarrow reg+1$		reg = 0
		rp1	1	1+S	$rp1 \leftarrow rp1+1$		rp1 = 00H
		@HL	2	2+S	$(HL) \leftarrow (HL)+1$	*1	(HL) = 0
		mem	2	2+S	$(mem) \leftarrow (mem)+1$	*3	(mem) = 0
	DECS	reg	1	1+S	$reg \leftarrow reg-1$		reg = FH
		rp'	2	2+S	$rp' \leftarrow rp'-1$		rp' = FFH
Comparison	SKE	reg, #n4	2	2+S	Skip if reg = n4		reg = n4
		@HL, #n4	2	2+S	Skip if (HL) = n4	*1	(HL) = n4
		A, @HL	1	1+S	Skip if A = (HL)	*1	A = (HL)
		XA, @HL	2	2+S	Skip if XA = (HL)	*1	XA = (HL)
		A, reg	2	2+S	Skip if A = reg		A = reg
		XA, rp'	2	2+S	Skip if XA = rp'		XA = rp'
Carry flag manipulation	SET1	CY	1	1	$CY \leftarrow 1$		
	CLR1	CY	1	1	$CY \leftarrow 0$		
	SKT	CY	1	1+S	Skip if CY = 1		CY = 1
	NOT1	CY	1	1	$CY \leftarrow \bar{CY}$		

Instruction Group	Mnemonic	Operand	Number of Bytes	Number of Machine Cycles	Operation	Addressing Area	Skip Condition
Memory bit manipulation	SET1	mem.bit	2	2	(mem.bit) ← 1	*3	
		fmem.bit	2	2	(fmem.bit) ← 1	*4	
		pmem.@L	2	2	(pmem ₇₋₂ +L ₃₋₂ .bit(L ₁₋₀)) ← 1	*5	
		@H+mem.bit	2	2	(H+mem ₃₋₀ .bit) ← 1	*1	
	CLR1	mem.bit	2	2	(mem.bit) ← 0	*3	
		fmem.bit	2	2	(fmem.bit) ← 0	*4	
		pmem.@L	2	2	(pmem ₇₋₂ +L ₃₋₂ .bit(L ₁₋₀)) ← 0	*5	
		@H+mem.bit	2	2	(H+mem ₃₋₀ .bit) ← 0	*1	
	SKT	mem.bit	2	2+S	Skip if (mem.bit)=1	*3	(mem.bit)=1
		fmem.bit	2	2+S	Skip if (fmem.bit)=1	*4	(fmem.bit)=1
		pmem.@L	2	2+S	Skip if (pmem ₇₋₂ +L ₃₋₂ .bit(L ₁₋₀))=1	*5	(pmem.@L)=1
		@H+mem.bit	2	2+S	Skip if (H+mem ₃₋₀ .bit)=1	*1	(@H+mem.bit)=1
	SKF	mem.bit	2	2+S	Skip if (mem.bit)=0	*3	(mem.bit)=0
		fmem.bit	2	2+S	Skip if (fmem.bit)=0	*4	(fmem.bit)=0
		pmem.@L	2	2+S	Skip if (pmem ₇₋₂ +L ₃₋₂ .bit(L ₁₋₀))=0	*5	(pmem.@L)=0
		@H+mem.bit	2	2+S	Skip if (H+mem ₃₋₀ .bit)=0	*1	(@H+mem.bit)=0
	SKTCLR	fmem.bit	2	2+S	Skip if (fmem.bit)=1 and clear	*4	(fmem.bit)=1
		pmem.@L	2	2+S	Skip if (pmem ₇₋₂ +L ₃₋₂ .bit(L ₁₋₀))=1 and clear	*5	(pmem.@L)=1
		@H+mem.bit	2	2+S	Skip if (H+mem ₃₋₀ .bit)=1 and clear	*1	(@H+mem.bit)=1
	AND1	CY, fmem.bit	2	2	CY ← CY ∧ (fmem.bit)	*4	
		CY, pmem.@L	2	2	CY ← CY ∧ (pmem ₇₋₂ +L ₃₋₂ .bit(L ₁₋₀))	*5	
		CY, @H+mem.bit	2	2	CY ← CY ∧ (H+mem ₃₋₀ .bit)	*1	
	OR1	CY, fmem.bit	2	2	CY ← CY ∨ (fmem.bit)	*4	
		CY, pmem.@L	2	2	CY ← CY ∨ (pmem ₇₋₂ +L ₃₋₂ .bit(L ₁₋₀))	*5	
CY, @H+mem.bit		2	2	CY ← CY ∨ (H+mem ₃₋₀ .bit)	*1		
XOR1	CY, fmem.bit	2	2	CY ← CY ⊕ (fmem.bit)	*4		
	CY, pmem.@L	2	2	CY ← CY ⊕ (pmem ₇₋₂ +L ₃₋₂ .bit(L ₁₋₀))	*5		
	CY, @H+mem.bit	2	2	CY ← CY ⊕ (H+mem ₃₋₀ .bit)	*1		

Instruction Group	Mnemonic	Operand	Number of Bytes	Number of Machine Cycles	Operation	Addressing Area	Skip Condition
Branch	BR ^{Note 1}	addr	–	–	PC ₁₃₋₀ ← addr (Select appropriate instruction from among the following instructions according to the assembler being used. BR !addr BRCB !caddr BR \$addr)	*6	
		addr1	–	–	● μPD753012A, 753016A PC ₁₃₋₀ ← addr1 (Select appropriate instruction from among the following instructions according to the assembler being used. BR !addr BRA !addr1 BRCB !caddr BR \$addr1)	*11	
					● μPD753017A PC ₁₄₋₀ ← addr1 (Select appropriate instruction from among the following instructions according to the assembler being used. BR !addr BRA !addr1 BRCB !caddr BR \$addr1)		
		!addr	3	3	PC ₁₃₋₀ ← addr ● μPD753017A PC ₁₄ ← 0, PC ₁₃₋₀ ← addr	*6	
		\$addr	1	2	PC ₁₃₋₀ ← addr	*7	
		\$addr1	1	2	● μPD753017A PC ₁₄₋₀ ← addr1		
		PCDE	2	3	PC ₁₃₋₀ ← PC ₁₃₋₈ +DE ● μPD753017A PC ₁₄₋₀ ← PC ₁₄₋₈ +DE		
		PCXA	2	3	PC ₁₃₋₀ ← PC ₁₃₋₈ +XA ● μPD753017A PC ₁₄₋₀ ← PC ₁₄₋₈ +XA		
		BCDE ^{Note 2}	2	3	PC ₁₃₋₀ ← BCDE ● μPD753017A PC ₁₄₋₀ ← BCDE	*6	
						*11	
		BCXA ^{Note 2}	2	3	PC ₁₃₋₀ ← BCXA ● μPD753017A PC ₁₄₋₀ ← BCXA	*6	
						*11	

Notes 1. The above operations in the shaded boxes can be performed only in the Mk II mode. The other operations can be performed only in the Mk I mode.

2. Only the following bits are valid for the B register.

μPD753012A, 753016A : low-order 2 bits

μPD753017A : low-order 3 bits

Remark When the μPD753017A is set in the Mk I mode, PC₁₄ is fixed to 0.

Instruction Group	Mnemonic	Operand	Number of Bytes	Number of Machine Cycles	Operation	Addressing Area	Skip Condition
Branch	BRA ^{Note}	!addr	3	3	● μPD753012A, 753016A PC ₁₃₋₀ ← addr	*6	
		!addr1	3	3	● μPD753017A PC ₁₄₋₀ ← addr1	*11	
	BRCB ^{Note}	!caddr	2	2	PC ₁₃₋₀ ← PC _{13,12} +caddr ₁₁₋₀ ● μPD753017A PC ₁₄₋₀ ← PC _{14,13,12} +caddr ₁₁₋₀	*8	
Subroutine stack control	CALLA ^{Note}	!addr	3	3	● μPD753012A, 753016A (SP-6)(SP-3)(SP-4) ← PC ₁₁₋₀ (SP-5) ← 0, 0, PC _{13, 12} (SP-2) ← X, X, MBE, RBE PC ₁₃₋₀ ← addr, SP ← SP-6	*6	
		!addr1	3	3	● μPD753017A (SP-6)(SP-3)(SP-4) ← PC ₁₁₋₀ (SP-5) ← 0, PC _{14, 13, 12} (SP-2) ← X, X, MBE, RBE PC ₁₄₋₀ ← addr1, SP ← SP-6	*11	
	CALL ^{Note}	!addr	3	3	(SP-4)(SP-1)(SP-2) ← PC ₁₁₋₀ (SP-3) ← MBE, RBE, PC ₁₃ , PC ₁₂ PC ₁₃₋₀ ← addr, SP ← SP-4	*6	
			4	4	● μPD753012A, 753016A (SP-6)(SP-3)(SP-4) ← PC ₁₁₋₀ (SP-5) ← 0, 0, PC _{13, 12} (SP-2) ← X, X, MBE, RBE PC ₁₃₋₀ ← addr, SP ← SP-6		
4			4	● μPD753017A (SP-6)(SP-3)(SP-4) ← PC ₁₁₋₀ (SP-5) ← 0, PC _{14, 13, 12} (SP-2) ← X, X, MBE, RBE PC ₁₄ ← 0, PC ₁₃₋₀ ← addr, SP ← SP-6			
CALLF ^{Note}	!faddr	2	2	(SP-4)(SP-1)(SP-2) ← PC ₁₁₋₀ (SP-3) ← MBE, RBE, PC ₁₃ , PC ₁₂ PC ₁₃₋₀ ← 000+faddr, SP ← SP-4	*9		
		3	3	● μPD753012A, 753016A (SP-6)(SP-3)(SP-4) ← PC ₁₁₋₀ (SP-5) ← 0, 0, PC _{13, 12} (SP-2) ← X, X, MBE, RBE PC ₁₃₋₀ ← 000+faddr, SP ← SP-6			
		3	3	● μPD753017A (SP-6)(SP-3)(SP-4) ← PC ₁₁₋₀ (SP-5) ← 0, PC _{14, 13, 12} (SP-2) ← X, X, MBE, RBE PC ₁₄₋₀ ← 0000+faddr, SP ← SP-6			

Note The above operations in the shaded boxes can be performed only in the Mk II mode. The other operations can be performed only in the Mk I mode.

Remark When the μPD753017A is set in the Mk I mode, PC₁₄ is fixed to 0.

Instruction Group	Mnemonic	Operand	Number of Bytes	Number of Machine Cycles	Operation	Addressing Area	Skip Condition
Subroutine stack control	RET ^{Note}		1	3	MBE, RBE, PC ₁₃ , PC ₁₂ ← (SP+1) PC ₁₁₋₀ ← (SP)(SP+3)(SP+2), SP ← SP+4 ● μPD753012A, 753016A X, X, MBE, RBE ← (SP+4) 0, 0, PC ₁₃ , PC ₁₂ ← (SP+1) PC ₁₁₋₀ ← (SP)(SP+3)(SP+2), SP ← SP+6 ● μPD753017A X, X, MBE, RBE ← (SP+4) 0, PC ₁₄ , PC ₁₃ , PC ₁₂ ← (SP+1) PC ₁₁₋₀ ← (SP)(SP+3)(SP+2), SP ← SP+6		
	RETS ^{Note}		1	3+S	MBE, RBE, PC ₁₃ , PC ₁₂ ← (SP+1) PC ₁₁₋₀ ← (SP)(SP+3)(SP+2), SP ← SP+4 then skip unconditionally ● μPD753012A, 753016A X, X, MBE, RBE ← (SP+4) 0, 0, PC ₁₃ , PC ₁₂ ← (SP+1) PC ₁₁₋₀ ← (SP)(SP+3)(SP+2), SP ← SP+6 then skip unconditionally ● μPD753017A X, X, MBE, RBE ← (SP+4) 0, PC ₁₄ , PC ₁₃ , PC ₁₂ ← (SP+1) PC ₁₁₋₀ ← (SP)(SP+3)(SP+2), SP ← SP+6 then skip unconditionally		Unconditional
	RETJ ^{Note}	!faddr	1	3	MBE, RBE, PC ₁₃ , PC ₁₂ ← (SP+1) PC ₁₁₋₀ ← (SP)(SP+3)(SP+2) PSW ← (SP+4)(SP+5), SP ← SP+6 ● μPD753012A, 753016A 0, 0, PC ₁₃ , PC ₁₂ ← (SP+1) PC ₁₁₋₀ ← (SP)(SP+3)(SP+2) PSW ← (SP+4)(SP+5), SP ← SP+6 ● μPD753017A 0, PC ₁₄ , PC ₁₃ , PC ₁₂ ← (SP+1) PC ₁₁₋₀ ← (SP)(SP+3)(SP+2) PSW ← (SP+4)(SP+5), SP ← SP+6		

Note The above operations in the shaded boxes can be performed only in the Mk II mode. The other operations can be performed only in the Mk I mode.

Remark When the μPD753017A is set in the Mk I mode, PC₁₄ is fixed to 0.

Instruction Group	Mnemonic	Operand	Number of Bytes	Number of Machine Cycles	Operation	Addressing Area	Skip Condition
Subroutine stack control	PUSH	rp	1	1	$(SP-1)(SP-2) \leftarrow rp, SP \leftarrow SP-2$		
		BS	2	2	$(SP-1) \leftarrow MBS, (SP-2) \leftarrow RBS, SP \leftarrow SP-2$		
	POP	rp	1	1	$rp \leftarrow (SP+1)(SP), SP \leftarrow SP+2$		
		BS	2	2	$MBS \leftarrow (SP+1), RBS \leftarrow (SP), SP \leftarrow SP+2$		
Interrupt control	EI		2	2	$IME(IPS.3) \leftarrow 1$		
		IEXXX	2	2	$IEXXX \leftarrow 1$		
	DI		2	2	$IME(IPS.3) \leftarrow 0$		
		IEXXX	2	2	$IEXXX \leftarrow 0$		
Input/output	IN ^{Note 1}	A, PORTn	2	2	$A \leftarrow PORTn \quad (n = 0-7)$		
		XA, PORTn	2	2	$XA \leftarrow PORTn+1, PORTn \quad (n = 4, 6)$		
	OUT ^{Note 1}	PORTn, A	2	2	$PORTn \leftarrow A \quad (n = 2-7)$		
		PORTn, XA	2	2	$PORTn+1, PORTn \leftarrow XA \quad (n = 4, 6)$		
CPU control	HALT		2	2	Set HALT mode ($PCC.2 \leftarrow 1$)		
	STOP		2	2	Set STOP mode ($PCC.3 \leftarrow 1$)		
	NOP		1	1	No operation		
Special	SEL	RBn	2	2	$RBS \leftarrow n \quad (n = 0-3)$		
		MBn	2	2	$MBS \leftarrow n \quad (n = 0-3, 15)$		
	GETI ^{Notes 2, 3}	taddr	1	3	<ul style="list-style-type: none"> When TBR instruction $PC_{13-0} \leftarrow (taddr)_{5-0}+(taddr+1)$ 	*10	Depending on the reference instruction
					<ul style="list-style-type: none"> When TCALL instruction $(SP-4)(SP-1)(SP-2) \leftarrow PC_{11-0}$ $(SP-3) \leftarrow MBE, RBE, PC_{13}, PC_{12}$ $PC_{13-0} \leftarrow (taddr)_{5-0}+(taddr+1)$ $SP \leftarrow SP-4$ 		
					<ul style="list-style-type: none"> When instruction other than TBR and TCALL instructions (taddr) (taddr+1) instruction is executed 		
			<ul style="list-style-type: none"> μPD753017A When TBR instruction $PC_{13-0} \leftarrow (taddr)_{5-0}+(taddr+1)$ $PC_{14} \leftarrow 0$ 				
4	4	<ul style="list-style-type: none"> When TCALL instruction $(SP-6)(SP-3)(SP-4) \leftarrow PC_{11-0}$ $(SP-5) \leftarrow 0, 0, PC_{13, 12}$ $(SP-2) \leftarrow X, X, MBE, RBE$ $PC_{13-0} \leftarrow (taddr)_{5-0}+(taddr+1)$ $SP \leftarrow SP-6, PC_{14} \leftarrow 0$ 	Depending on the reference instruction				
		<ul style="list-style-type: none"> When instruction other than TBR and TCALL instructions (taddr) (taddr+1) instruction is executed 					

- Notes 1.** While the IN instruction and OUT instruction are being executed, the MBE must be set to 0 or 1 and MBS must be set to 15.
- 2.** The above operations in the shaded boxes can be performed only in the Mk II mode. The other operations can be performed only in the Mk I mode.
- 3.** The TBR and TCALL instructions are the table definition assembler pseudo instructions of the GETI instruction.

Remark When the μPD753017A is set in the Mk I mode, PC₁₄ is fixed to 0.

12. ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings (T_A = 25°C)

Parameter	Symbol	Conditions		Ratings	Unit
Supply voltage	V _{DD}			-0.3 to +7.0	V
Input voltage	V _{I1}	Other than ports 4, 5		-0.3 to V _{DD} + 0.3	V
	V _{I2}	Ports 4, 5	Pull-up resistor provided	-0.3 to V _{DD} + 0.3	V
			N-ch open-drain	-0.3 to +14	V
Output voltage	V _O			-0.3 to V _{DD} + 0.3	V
High-level output current	I _{OH}	Per pin		-10	mA
		Total of all pins		-30	mA
Low-level output current	I _{OL}	Per pin		30	mA
		Total of all pins		220	mA
Operating ambient temperature	T _A			-40 to +85	°C
Storage temperature	T _{stg}			-65 to +150	°C

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Capacitance (T_A = 25°C, V_{DD} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input capacitance	C _{IN}	f = 1 MHz			15	pF
Output capacitance	C _{OUT}	Unmeasured pins returned to 0 V			15	pF
I/O capacitance	C _{IO}				15	pF

Main System Clock Oscillator Characteristics (T_A = -40 to +85°C, V_{DD} = 1.8 to 5.5 V)

Resonator	Recommended Circuit	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
Ceramic resonator		Oscillation frequency (f _x) ^{Note 1}		1.0		6.0 ^{Note 2}	MHz
		Oscillation stabilization time ^{Note 3}	After V _{DD} has reached MIN. value of oscillation voltage range			4	ms
Crystal resonator		Oscillation frequency (f _x) ^{Note 1}		1.0		6.0 ^{Note 2}	MHz
		Oscillation stabilization time ^{Note 3}	V _{DD} = 4.5 to 5.5 V			10	ms
						30	
External clock		X1 input frequency (f _x) ^{Note 1}		1.0		6.0 ^{Note 2}	MHz
		X1 input high-, low-level width (t _{xH} , t _{xL})		83.3		500	ns

- Notes 1.** The oscillation frequency and X1 input frequency shown above indicate characteristics of the oscillator only. For the instruction execution time, refer to **AC Characteristics**.
- If the oscillation frequency is 4.19 MHz < f_x ≤ 6.0 MHz at 1.8 V ≤ V_{DD} < 2.7 V, do not set the processor clock control register (PCC) to 0011. If PCC = 0011, one machine cycle time is less than 0.95 μs, falling short of the rated value of 0.95 μs.
 - The oscillation stabilization time is the time required for oscillation to be stabilized after V_{DD} has been applied or STOP mode has been released.

Caution When using the main system clock oscillator, wire the portion enclosed in the dotted line in the above figure as follows to prevent adverse influence due to wiring capacitance:

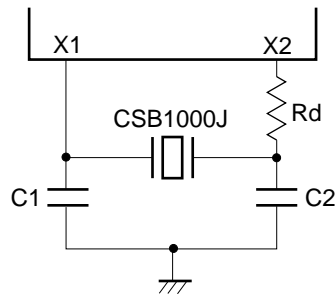
- Keep the wiring length as short as possible.
- Do not cross the wiring with other signal lines.
- Do not route the wiring in the vicinity of a line through which a high alternating current flows.
- Always keep the ground point of the capacitor of the oscillator at the same potential as V_{DD}.
- Do not ground to a power supply pattern through which a high current flows.
- Do not extract signals from the oscillator.

Recommended Oscillator Constant

Ceramic resonator (T_A = -20 to +80°C)

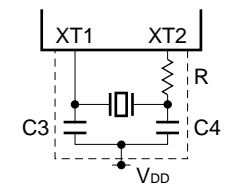
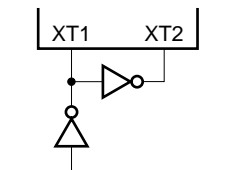
Manufacturer	Part Number	Frequency (MHz)	Recommended Circuit Constant (pF)		Oscillation Voltage Range (V)		Remarks	
			C1	C2	MIN.	MAX.		
TDK Corp.	CCR1000K2	1.0	100	100	1.8	5.5	-	
	CCR2.0MC33	2.0	-	-			On-chip capacitor	
	CCR4.19MC3	4.19	-	-				
	FCR4.19MC5		-	-				
	CCR6.0MC3	6.0	-	-				
Murata Mfg. Co., Ltd.	CSB1000J ^{Note}	1.0	100	100	2.1	5.5	Rd = 5.6 kΩ	
	CSA2.00MG040	2.0	100	100	1.9		-	
	CST2.00MG040		-	-	On-chip capacitor			
	CSA4.19MG	4.19	30	30			1.8	-
	CST4.19MGW		-	-			On-chip capacitor	
	CSA6.00MG	6.0	30	30	2.3			-
	CST6.00MGW		-	-	On-chip capacitor			
Kyocera Corp.	KBR-1000F/Y	1.0	100	100		1.8	5.5	-
	KBR-2.0MS	2.0	68	68				
	KBR-4.0MSA/MSB	4.0	33	33	On-chip capacitor			
	KBR-4.0MKC		-	-				
	KBR-4.0MKD		-	-				
	KBR-4.0MKS		-	-				
	PBRC4.00A	4.0	33	33	-			
	PBRC4.00B		-	-	On-chip capacitor			
	KBR-4.19MSA	4.19	33	33				-
	KBR-4.19MSB		33	33				
	KBR-4.19MKC		-	-	On-chip capacitor			
	KBR-4.19MKD		-	-				
	KBR-4.19MKS		-	-				
	PBRC4.19A		33	33	-			
	PBRC4.19B	-	-	On-chip capacitor				
	KBR-6.0MSA/MSB	6.0	33		33			-
	KBR-6.0MKC		-	-	On-chip capacitor			
	KBR-6.0MKD		-	-				
	KBR-6.0MKS		-	-				
	PBRC6.00A		33	33	-			
PBRC6.00B	-		-	On-chip capacitor				

Note When using the CSB1000J (1.0 MHz) by Murata Mfg. Co., Ltd. as a ceramic resonator, a limiting resistor ($R_d = 5.6 \text{ k}\Omega$) is necessary (refer to the figure below). The resistor is not necessary when using the other recommended resonators.



Caution The oscillator constant and oscillation voltage range indicate conditions of stable oscillation. Oscillation frequency precision is not guaranteed. For applications requiring oscillation frequency precision, the oscillation frequency must be adjusted on the implementation circuit. For details, please contact directly the manufacturer of the resonator you will use.

Subsystem Clock Oscillator Characteristics (T_A = -40 to +85°C, V_{DD} = 1.8 to 5.5 V)

Resonator	Recommended Circuit	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
Crystal resonator		Oscillation frequency (f _{X_T}) ^{Note 1}		32	32.768	35	kHz
		Oscillation stabilization time ^{Note 2}	V _{DD} = 4.5 to 5.5 V		1.0	2	ms
External clock		XT1 input frequency (f _{X_T}) ^{Note 1}		32		100	kHz
		XT1 input high-, low-level width (t _{X_TH} , t _{X_TL})		5		15	μs

- Notes 1.** The oscillation frequency shown above indicates characteristics of the oscillator only. For the instruction execution time, refer to **AC Characteristics**.
- 2.** The oscillation stabilization time is the time required for oscillation to be stabilized after V_{DD} has been applied.

Caution When using the subsystem clock oscillator, wire the portion enclosed in the dotted line in the above figure as follows to prevent adverse influence due to wiring capacitance:

- Keep the wiring length as short as possible.
- Do not cross the wiring with other signal lines.
- Do not route the wiring in the vicinity of a line through which a high alternating current flows.
- Always keep the ground point of the capacitor of the oscillator at the same potential as V_{DD}.
- Do not ground to a power supply pattern through which a high current flows.
- Do not extract signals from the oscillation circuit.

The subsystem clock oscillator has a low amplification factor to reduce current consumption and is more susceptible to noise than the main system clock oscillator. Therefore, exercise utmost care in wiring the subsystem clock oscillator.

★ **Remark** For the resonator selection and oscillator constant, customers are requested to either evaluate the oscillation themselves or apply to the resonator manufacturer for evaluation.

DC Characteristics (T_A = -40 to +85°C, V_{DD} = 1.8 to 5.5 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit	
Low-level output current	I _{OL}	Per pin				15	mA	
		Total of all pins				150	mA	
High-level input voltage	V _{IH1}	Ports 2, 3		V _{DD} = 2.7 to 5.5 V	0.7 V _{DD}	V _{DD}	V	
				V _{DD} = 1.8 to 2.7 V	0.9 V _{DD}	V _{DD}	V	
	V _{IH2}	Ports 0, 1, 6, 7, $\overline{\text{RESET}}$		V _{DD} = 2.7 to 5.5 V	0.8 V _{DD}	V _{DD}	V	
				V _{DD} = 1.8 to 2.7 V	0.9 V _{DD}	V _{DD}	V	
	V _{IH3}	Ports 4, 5	Pull-up resistor provided	V _{DD} = 2.7 to 5.5 V	0.7 V _{DD}	V _{DD}	V	
				V _{DD} = 1.8 to 2.7 V	0.9 V _{DD}	V _{DD}	V	
			N-ch open-drain	V _{DD} = 2.7 to 5.5 V	0.7 V _{DD}	13	V	
				V _{DD} = 1.8 to 2.7 V	0.9 V _{DD}	13	V	
V _{IH4}	X1, XT1		V _{DD} -0.1		V _{DD}	V		
Low-level input voltage	V _{IL1}	Ports 2, 3, 4, 5		V _{DD} = 2.7 to 5.5 V	0	0.3 V _{DD}	V	
				V _{DD} = 1.8 to 2.7 V	0	0.1 V _{DD}	V	
	V _{IL2}	Ports 0, 1, 6, 7, $\overline{\text{RESET}}$		V _{DD} = 2.7 to 5.5 V	0	0.2 V _{DD}	V	
				V _{DD} = 1.8 to 2.7 V	0	0.1 V _{DD}	V	
V _{IL3}	X1, XT1		0		0.1	V		
High-level output voltage	V _{OH}	$\overline{\text{SCK}}$, SO, Ports 2, 3, 6, 7, BP0-BP7 I _{OH} = -1 mA		V _{DD} -0.5			V	
Low-level output voltage	V _{OL1}	$\overline{\text{SCK}}$, SO, Ports 2-7, BP0-BP7		I _{OL} = 15 mA V _{DD} = 5.0 V ±10%		0.2	2.0	V
				I _{OL} = 1.6 mA			0.4	V
V _{OL2}	SB0, SB1	N-ch open-drain Pull-up resistor ≥ 1 kΩ				0.2 V _{DD}	V	
High-level input leakage current	I _{LIH1}	V _{IN} = V _{DD}	Pins other than X1, XT1, ports 4, 5				3	μA
	I _{LIH2}		X1, XT1				20	μA
	I _{LIH3}	V _{IN} = 13 V	Ports 4, 5 (N-ch open-drain)				20	μA
Low-level input leakage current	I _{LIL1}	V _{IN} = 0 V	Pins other than X1, XT1, ports 4, 5				-3	μA
	I _{LIL2}		X1, XT1				-20	μA
	I _{LIL3}		Ports 4, 5 (N-ch open-drain) When input instruction is not executed				-3	μA
		Ports 4, 5 (N-ch open-drain) When input instruction is executed	V _{DD} = 5 V		-10	-27	μA	
	V _{DD} = 3 V			-3	-8	μA		
High-level output leakage current	I _{LOH1}	V _{OUT} = V _{DD}	$\overline{\text{SCK}}$, SO/SB0, SB1, ports 2, 3, 6, 7, ports 4, 5 (pull-up resistor provided), BP0-BP7				3	μA
	I _{LOH2}	V _{OUT} = 13 V	Ports 4, 5 (N-ch open-drain)				20	μA
Low-level output leakage current	I _{LOL}	V _{OUT} = 0 V				-3	μA	
Internal pull-up resistor	R _{L1}	V _{IN} = 0 V	Ports 0, 1, 2, 3, 6, 7 (except P00 pin)		50	100	200	kΩ
	R _{L2}		Ports 4, 5 (mask option selected)		15	30	60	kΩ

★

DC Characteristics (T_A = -40 to +85°C, V_{DD} = 1.8 to 5.5 V)

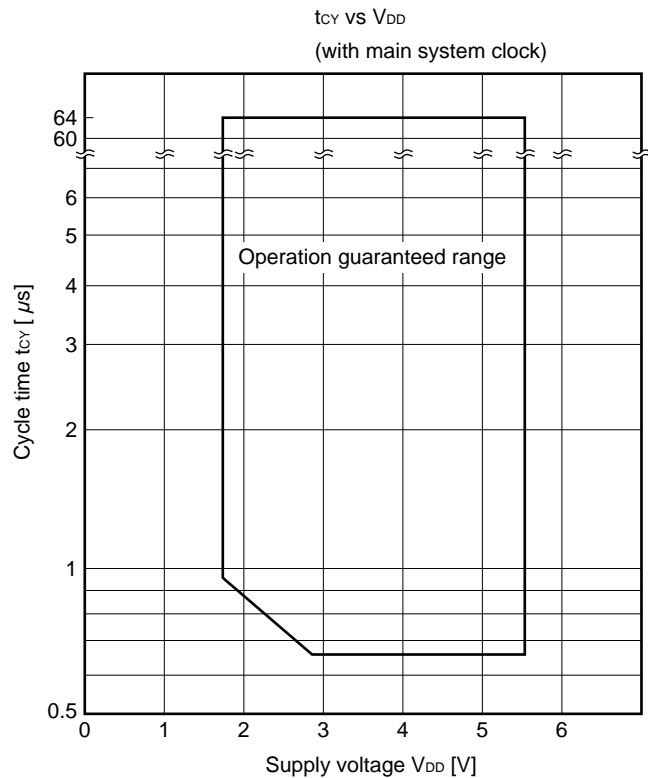
Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit	
LCD drive voltage ^{Note 1}	V _{LCD}	VAC0 = 0		2.2		V _{DD}	V	
		VAC0 = 1		1.8		V _{DD}	V	
VAC current ^{Note 2}	I _{VAC}	VAC0 = 1, V _{DD} = 2.0 V ±10%			1	4	μA	
LCD split resistor ^{Note 3}	R _{LCD1}			50	100	200	kΩ	
	R _{LCD2}			5	10	20	kΩ	
LCD output voltage deviation ^{Note 4} (common)	V _{ODC}	I _o = ±1.0 μA	V _{LCD0} = V _{LCD}	0		±0.2	V	
			V _{LCD1} = V _{LCD} × 2/3					
LCD output voltage deviation ^{Note 4} (segment)	V _{ODS}	I _o = ±0.5 μA	1.8 V ≤ V _{LCD} ≤ V _{DD}	0		±0.2	V	
Supply current ^{Notes 2, 5}	I _{DD1}	6.00 MHz ^{Note 6} crystal oscillation C1 = C2 = 22 pF	V _{DD} = 5.0 V ±10% ^{Note 7}			2.2	6.6	mA
			V _{DD} = 3.0 V ±10% ^{Note 8}			0.6	2.0	mA
	I _{DD2}		HALT mode	V _{DD} = 5.0 V ±10%		0.72	2.1	mA
				V _{DD} = 3.0 V ±10%		0.27	0.8	mA
	I _{DD1}	4.19 MHz ^{Note 6} crystal oscillation C1 = C2 = 22 pF	V _{DD} = 5.0 V ±10% ^{Note 7}			1.7	5.1	mA
			V _{DD} = 3.0 V ±10% ^{Note 8}			0.3	0.9	mA
	I _{DD2}		HALT mode	V _{DD} = 5.0 V ±10%		0.7	2.0	mA
				V _{DD} = 3.0 V ±10%		0.23	0.7	mA
	I _{DD3}	32.768 kHz ^{Note 9} crystal oscillation	Low voltage mode ^{Note 10}	V _{DD} = 3.0 V ±10%		15	45	μA
				V _{DD} = 2.0 V ±10%		8	24	μA
			Low current consumption mode ^{Note 11}	V _{DD} = 3.0 V, T _A = 25°C		15	30	μA
				V _{DD} = 3.0 V ±10%		12	36	μA
I _{DD4}		HALT mode	V _{DD} = 3.0 V ±10%		8.5	25	μA	
			V _{DD} = 2.0 V ±10%		4	12	μA	
		Low current consumption mode ^{Note 11}	V _{DD} = 3.0 V, T _A = 25°C		8.5	17	μA	
			V _{DD} = 3.0 V ±10%		3.5	12	μA	
I _{DD5}	XT1 = 0 V ^{Note 12} STOP mode	V _{DD} = 5.0 V ±10%			0.05	10	μA	
		V _{DD} = 3.0 V ±10%			0.02	5	μA	
			T _A = 25°C		0.02	3	μA	

- Notes**
- When 1.8 V ≤ V_{DD} < 2.7 V, T_A = -10 to +85°C.
 - Clear VAC0 to 0 in the low current consumption mode and STOP mode. When VAC0 is set to 1, the current increases by about 1 μA.
 - Either R_{LCD1} or R_{LCD2} can be selected by mask option.
 - Voltage deviation is the difference between the ideal values (V_{LCDn}; n = 0, 1, 2) of the segment and common outputs and the output voltage.
 - The current flowing through the internal pull-up resistor and the LCD divider resistor is not included.
 - Including the case when the subsystem clock oscillates.
 - When the device operates in high-speed mode with the processor clock control register (PCC) set to 0011.
 - When the device operates in low-speed mode with PCC set to 0000.
 - When the device operates on the subsystem clock, with the system clock control register (SCC) set to 1001 and oscillation of the main system clock stopped.
 - When the sub-oscillator control register (SOS) is set to 0000.
 - When SOS is set to 0010.
 - When SOS is set to 00X1, and the feedback resistor of the sub-oscillator is not used (X: don't care).

AC Characteristics (T_A = -40 to +85°C, V_{DD} = 1.8 to 5.5 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
CPU clock cycle time ^{Note 1} (minimum instruction execution time = 1 machine cycle)	t _{cy}	Operates with main system clock	V _{DD} = 2.7 to 5.5 V	0.67		64	μs
				0.95		64	μs
		Operates with subsystem clock		114	122	125	μs
T10, T11, T12 input frequency	f _{Ti}	V _{DD} = 2.7 to 5.5 V		0		1	MHz
				0		275	kHz
T10, T11, T12 input high-, low-level width	t _{TIH} , t _{TIL}	V _{DD} = 2.7 to 5.5 V		0.48			μs
				1.8			μs
Interrupt input high-, low-level width	t _{INTH} , t _{INTL}	INT0	IM02 = 0	Note 2			μs
			IM02 = 1	10			μs
		INT1, 2, 4		10			μs
		KR0-KR7		10			μs
RESET low-level width	t _{RSL}			10			μs

- Notes 1.** The cycle time of the CPU clock (Φ) is determined by the oscillation frequency of the connected resonator, the system clock control register (SCC), and processor clock control register (PCC). The figure on the right shows the supply voltage V_{DD} vs. cycle time t_{cy} characteristics when the device operates with the main system clock.
- 2.** 2t_{cy} or 128/f_x depending on the setting of the interrupt mode register (IM0).



Serial transfer operation

2-wire and 3-wire serial I/O modes ($\overline{\text{SCK}}$... internal clock output): ($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = 1.8$ to 5.5 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
$\overline{\text{SCK}}$ cycle time	t_{KCY1}	$V_{DD} = 2.7$ to 5.5 V	1300			ns	
			3800			ns	
$\overline{\text{SCK}}$ high-, low-level width	t_{KL1}	$V_{DD} = 2.7$ to 5.5 V	$t_{\text{KCY1}}/2-50$			ns	
	t_{KH1}		$t_{\text{KCY1}}/2-150$			ns	
SI ^{Note 1} setup time (to $\overline{\text{SCK}}$ ↑)	t_{SIK1}	$V_{DD} = 2.7$ to 5.5 V	150			ns	
			500			ns	
SI ^{Note 1} hold time (from $\overline{\text{SCK}}$ ↑)	t_{KSI1}	$V_{DD} = 2.7$ to 5.5 V	400			ns	
			600			ns	
$\overline{\text{SCK}}$ ↓ → SO ^{Note 1} output delay time	t_{KSO1}	$R_L = 1$ kΩ, ^{Note 2} $C_L = 100$ pF	$V_{DD} = 2.7$ to 5.5 V	0		250	ns
				0		1000	ns

Notes 1. Read as SB0 or SB1 when using the 2-wire serial I/O mode.

2. R_L and C_L respectively indicate the load resistance and load capacitance of the SO output line.

2-wire and 3-wire serial I/O modes ($\overline{\text{SCK}}$... external clock input): ($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = 1.8$ to 5.5 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
$\overline{\text{SCK}}$ cycle time	t_{KCY2}	$V_{DD} = 2.7$ to 5.5 V	800			ns	
			3200			ns	
$\overline{\text{SCK}}$ high-, low-level width	t_{KL2}	$V_{DD} = 2.7$ to 5.5 V	400			ns	
	t_{KH2}		1600			ns	
SI ^{Note 1} setup time (to $\overline{\text{SCK}}$ ↑)	t_{SIK2}	$V_{DD} = 2.7$ to 5.5 V	100			ns	
			150			ns	
SI ^{Note 1} hold time (from $\overline{\text{SCK}}$ ↑)	t_{KSI2}	$V_{DD} = 2.7$ to 5.5 V	400			ns	
			600			ns	
$\overline{\text{SCK}}$ ↓ → SO ^{Note 1} output delay time	t_{KSO2}	$R_L = 1$ kΩ, ^{Note 2} $C_L = 100$ pF	$V_{DD} = 2.7$ to 5.5 V	0		300	ns
				0		1000	ns

Notes 1. Read as SB0 or SB1 when using the 2-wire serial I/O mode.

2. R_L and C_L respectively indicate the load resistance and load capacitance of the SO output line.

SBI mode ($\overline{\text{SCK}}$... internal clock output (master)): ($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = 1.8$ to 5.5 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
$\overline{\text{SCK}}$ cycle time	t_{KCY3}	$V_{DD} = 2.7$ to 5.5 V	1300			ns
			3800			ns
$\overline{\text{SCK}}$ high-, low-level width	t_{KL3}	$V_{DD} = 2.7$ to 5.5 V	$t_{\text{KCY3}}/2-50$			ns
	t_{KH3}		$t_{\text{KCY3}}/2-150$			ns
SB0, 1 setup time (to $\overline{\text{SCK}}$ \uparrow)	t_{SIK3}	$V_{DD} = 2.7$ to 5.5 V	150			ns
			500			ns
SB0, 1 hold time (from $\overline{\text{SCK}}$ \uparrow)	t_{KSI3}		$t_{\text{KCY3}}/2$			ns
$\overline{\text{SCK}}$ \downarrow \rightarrow SB0, 1 output delay time	t_{KSO3}	$R_L = 1$ k Ω , ^{Note} $C_L = 100$ pF	$V_{DD} = 2.7$ to 5.5 V		250	ns
				0	1000	ns
$\overline{\text{SCK}}$ \uparrow \rightarrow SB0, 1 \downarrow	t_{KSB}		t_{KCY3}			ns
SB0, 1 \downarrow \rightarrow $\overline{\text{SCK}}$ \downarrow	t_{SBK}		t_{KCY3}			ns
SB0, 1 low-level width	t_{SBL}		t_{KCY3}			ns
SB0, 1 high-level width	t_{SBH}		t_{KCY3}			ns

Note R_L and C_L respectively indicate the load resistance and load capacitance of the SB0, 1 output line.

SBI mode ($\overline{\text{SCK}}$... external clock input (slave)): ($T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} = 1.8$ to 5.5 V)

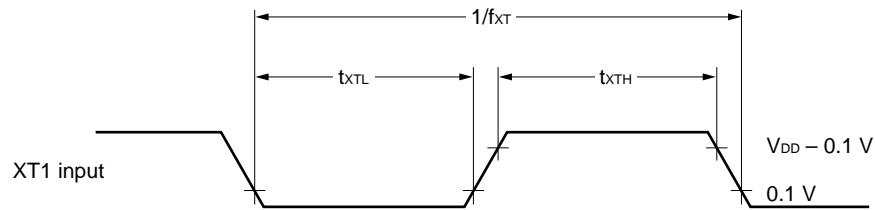
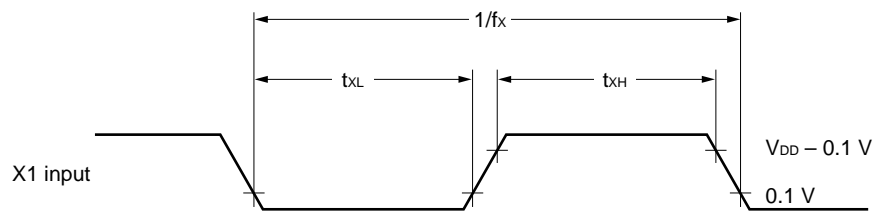
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
$\overline{\text{SCK}}$ cycle time	t_{KCY4}	$V_{DD} = 2.7$ to 5.5 V	800			ns
			3200			ns
$\overline{\text{SCK}}$ high-, low-level width	t_{KL4}	$V_{DD} = 2.7$ to 5.5 V	400			ns
	t_{KH4}		1600			ns
SB0, 1 setup time (to $\overline{\text{SCK}}$ \uparrow)	t_{SIK4}	$V_{DD} = 2.7$ to 5.5 V	100			ns
			150			ns
SB0, 1 hold time (from $\overline{\text{SCK}}$ \uparrow)	t_{KSI4}		$t_{\text{KCY4}}/2$			ns
$\overline{\text{SCK}}$ \downarrow \rightarrow SB0, 1 output delay time	t_{KSO4}	$R_L = 1$ k Ω , ^{Note} $C_L = 100$ pF	$V_{DD} = 2.7$ to 5.5 V		300	ns
				0	1000	ns
$\overline{\text{SCK}}$ \uparrow \rightarrow SB0, 1 \downarrow	t_{KSB}		t_{KCY4}			ns
SB0, 1 \downarrow \rightarrow $\overline{\text{SCK}}$ \downarrow	t_{SBK}		t_{KCY4}			ns
SB0, 1 low-level width	t_{SBL}		t_{KCY4}			ns
SB0, 1 high-level width	t_{SBH}		t_{KCY4}			ns

Note R_L and C_L respectively indicate the load resistance and load capacitance of the SB0, 1 output line.

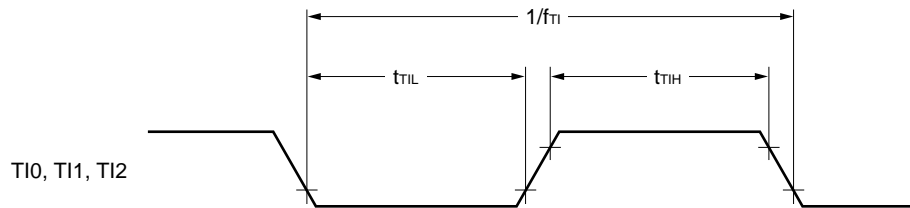
AC timing test points (except X1 and XT1 inputs)



Clock timing

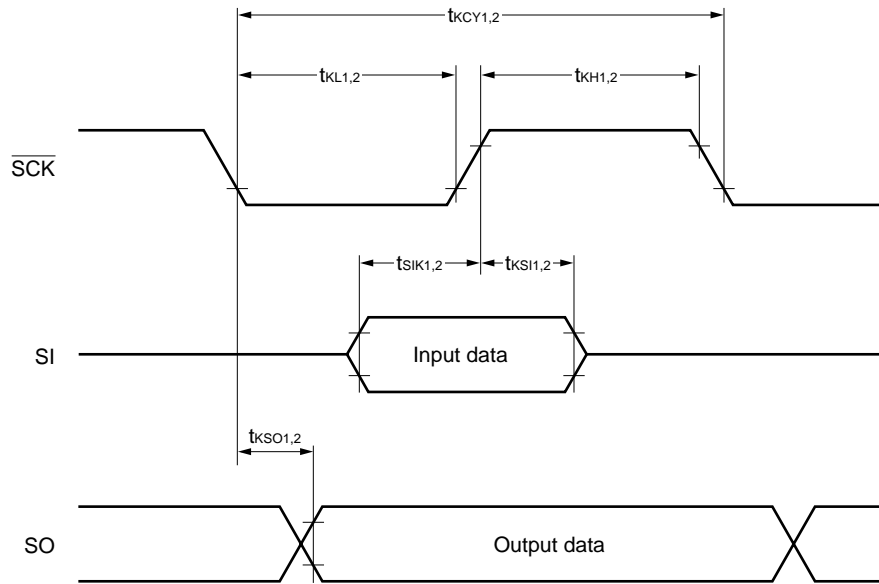


T10, T11, T12 timing

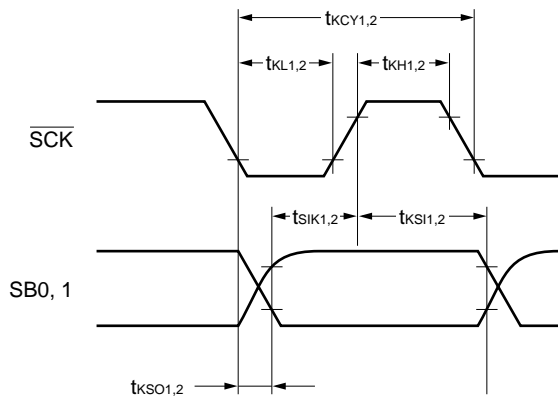


Serial transfer timing

3-wire serial I/O mode

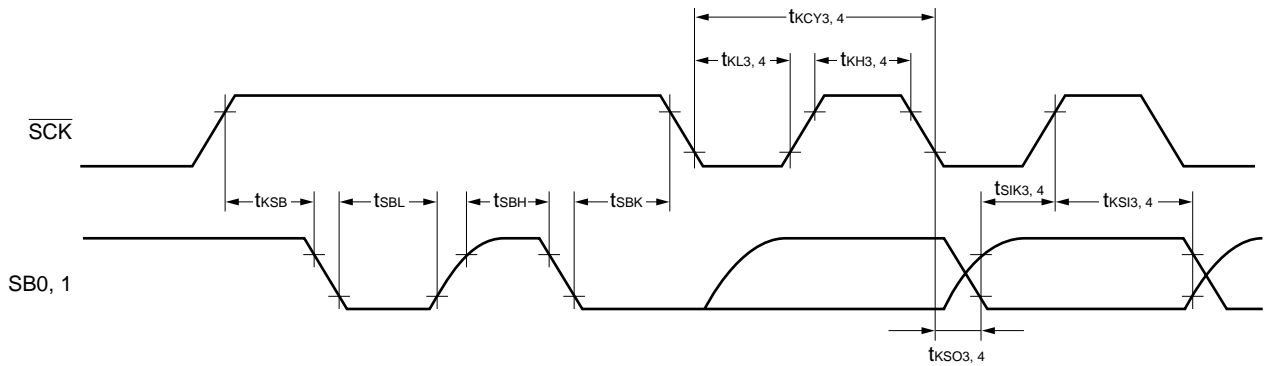


2-wire serial I/O mode

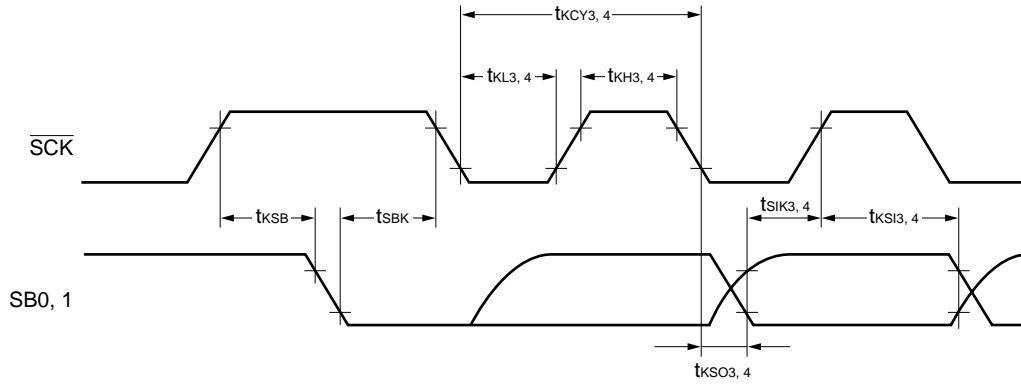


Serial transfer timing

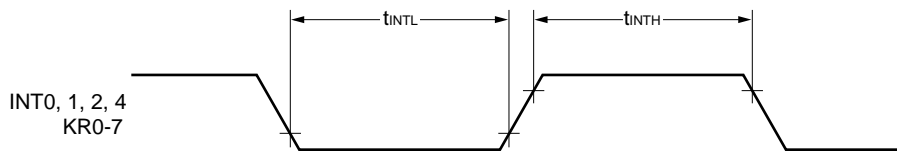
Bus release signal transfer



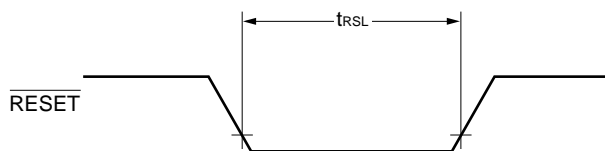
Command signal transfer



Interrupt input timing



$\overline{\text{RESET}}$ input timing



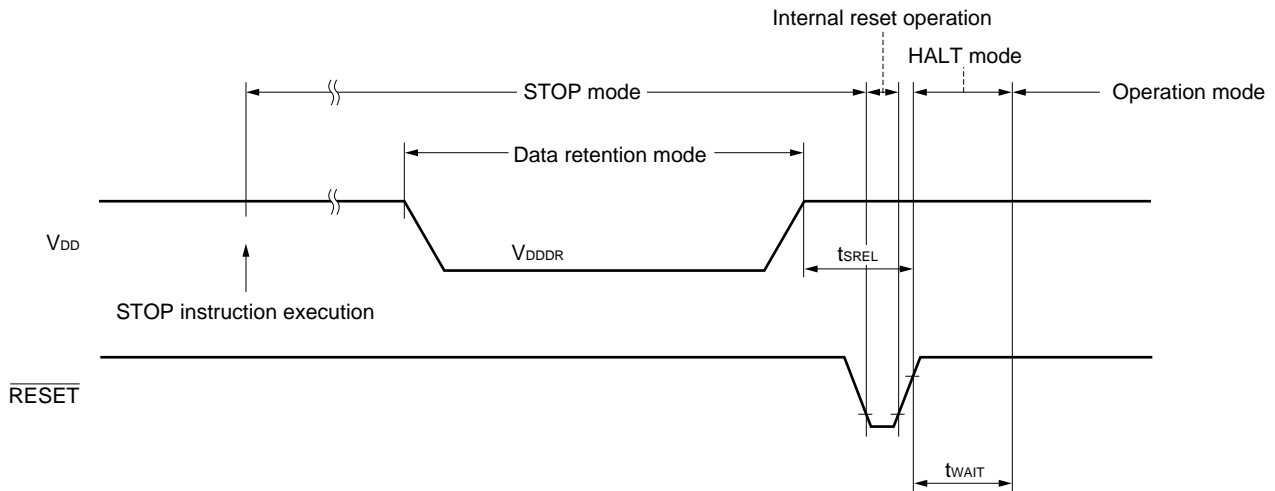
Data retention characteristics of data memory in STOP mode and at low supply voltage
 (T_A = -40 to +85°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
★ Data retention power supply voltage	V _{DDDR}		1.8		5.5	V
Release signal setup time	t _{SREL}		0			μs
Oscillation stabilization wait time ^{Note 1}	t _{WAIT}	Released by $\overline{\text{RESET}}$		Note 2		ms
		Released by interrupt request		Note 3		ms

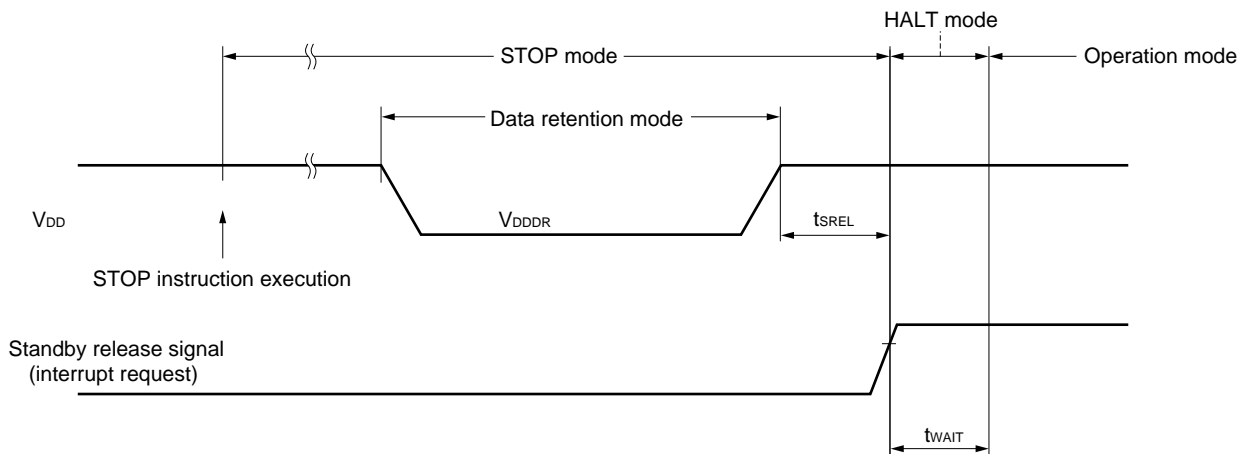
- Notes 1.** The oscillation stabilization wait time is the time during which the CPU stops operating to prevent unstable operation when oscillation is started.
- 2.** Either 2¹⁷/f_x or 2¹⁵/f_x can be selected by mask option.
- 3.** Set by the basic interval timer mode register (BTM). (Refer to the table below.)

BTM3	BTM2	BTM1	BTM0	Wait Time	
				f _x = 4.19 MHz	f _x = 6.0 MHz
-	0	0	0	2 ²⁰ /f _x (approx. 250 ms)	2 ²⁰ /f _x (approx. 175 ms)
-	0	1	1	2 ¹⁷ /f _x (approx. 31.3 ms)	2 ¹⁷ /f _x (approx. 21.8 ms)
-	1	0	1	2 ¹⁵ /f _x (approx. 7.81 ms)	2 ¹⁵ /f _x (approx. 5.46 ms)
-	1	1	1	2 ¹³ /f _x (approx. 1.95 ms)	2 ¹³ /f _x (approx. 1.37 ms)

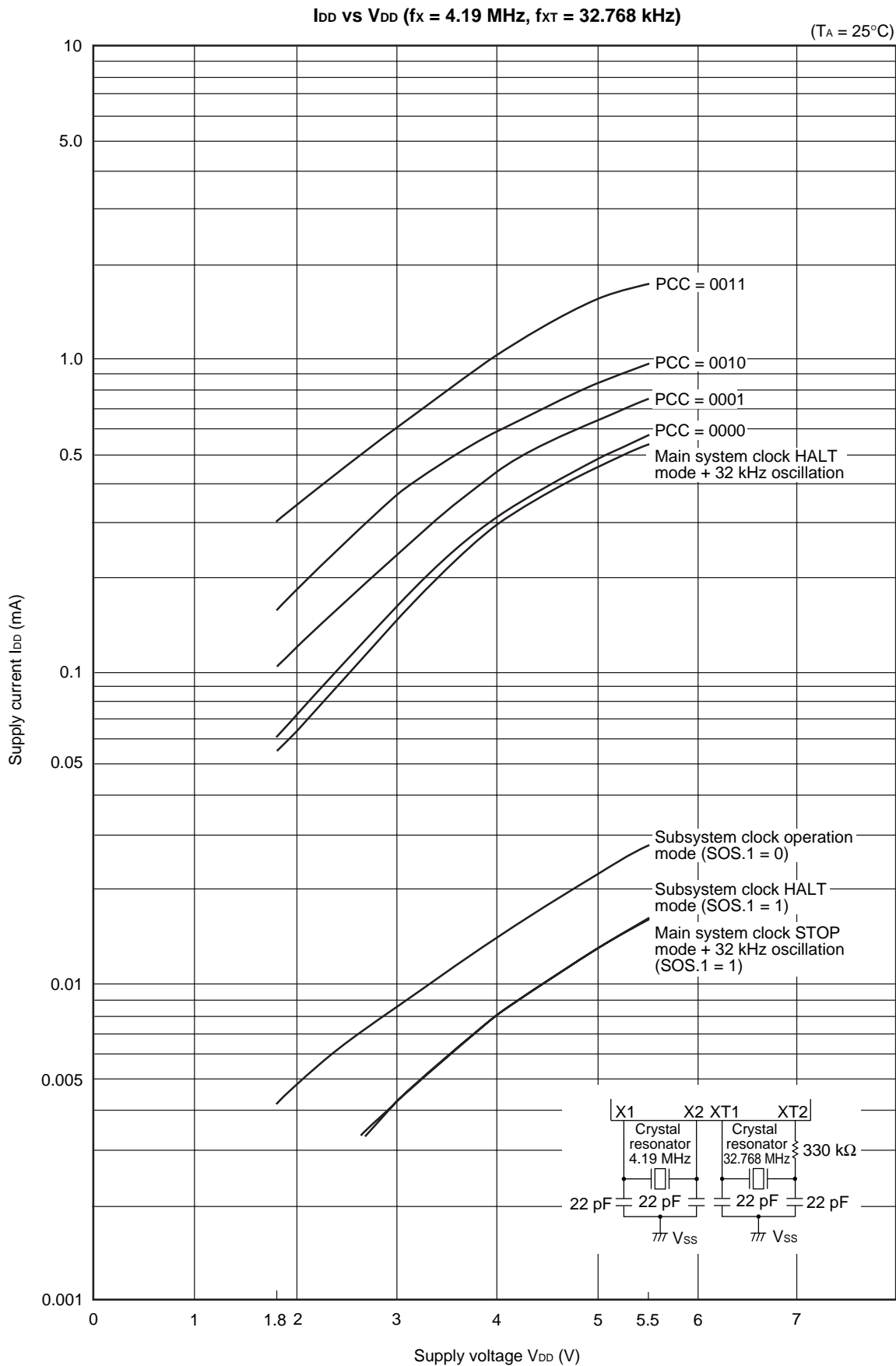
Data retention timing (when STOP mode released by $\overline{\text{RESET}}$)



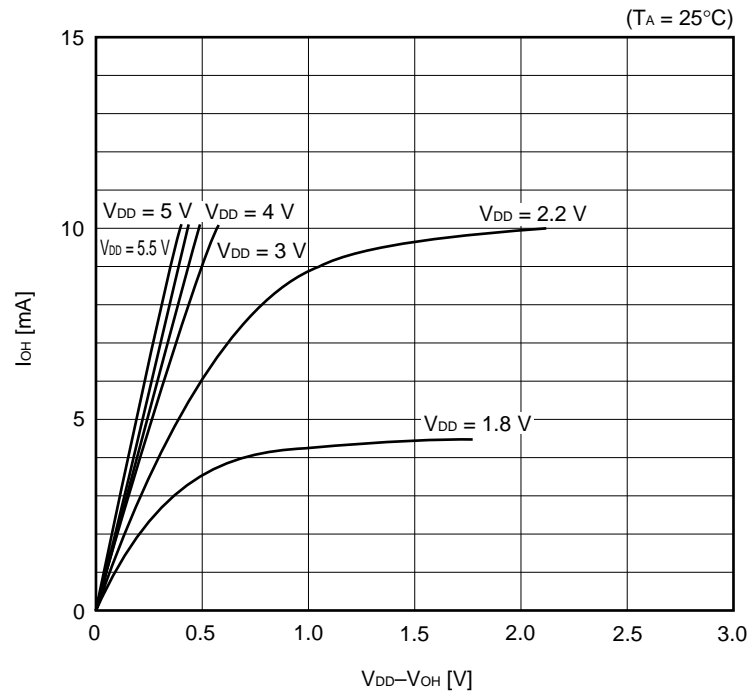
Data retention timing (standby release signal: when STOP mode released by interrupt signal)



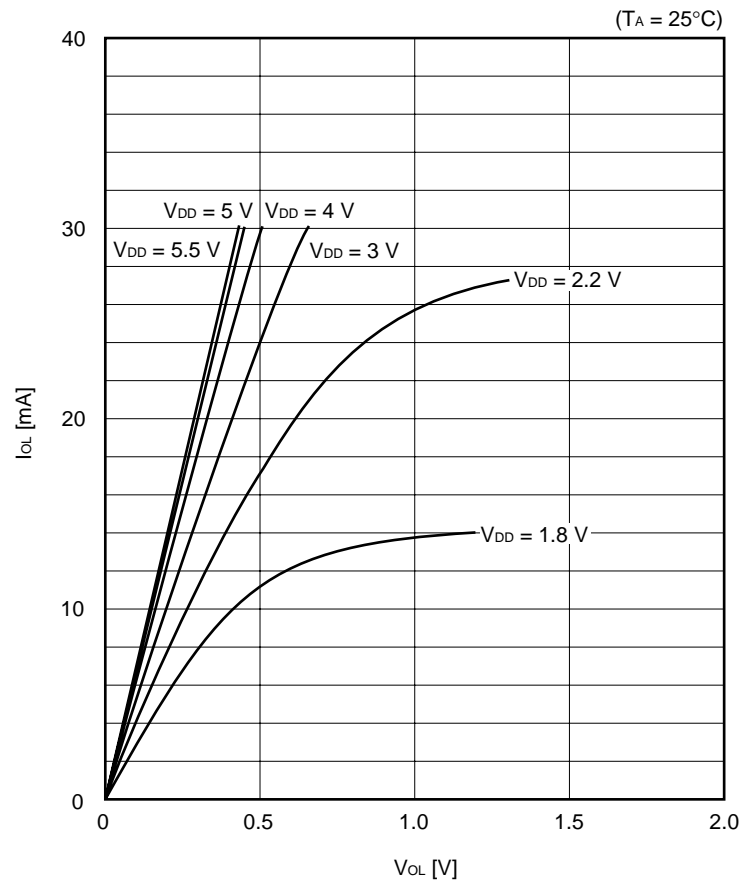
★ 13. CHARACTERISTICS CURVES (REFERENCE VALUES)



I_{OH} vs $V_{DD}-V_{OH}$ (Ports 2, 3, 6, 7)

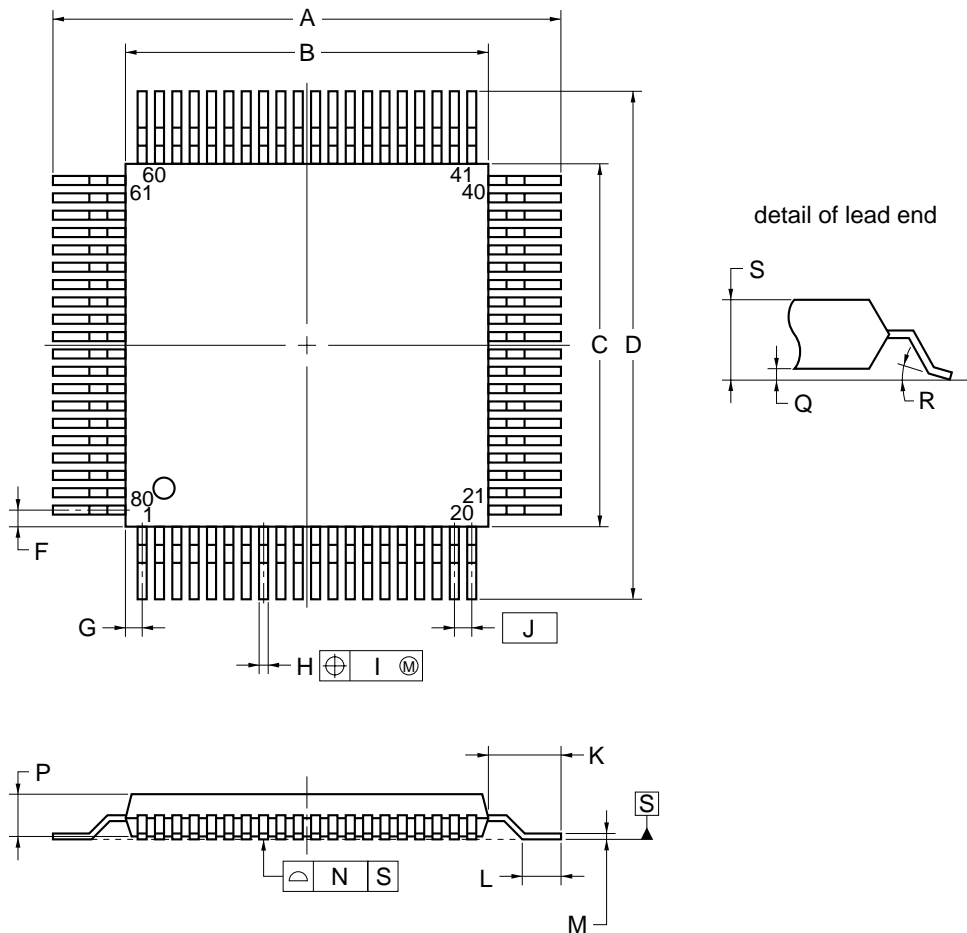


I_{OL} vs V_{OL} (Ports 2, 3, 6, 7)



14. PACKAGE DRAWINGS

80-PIN PLASTIC QFP (14x14)

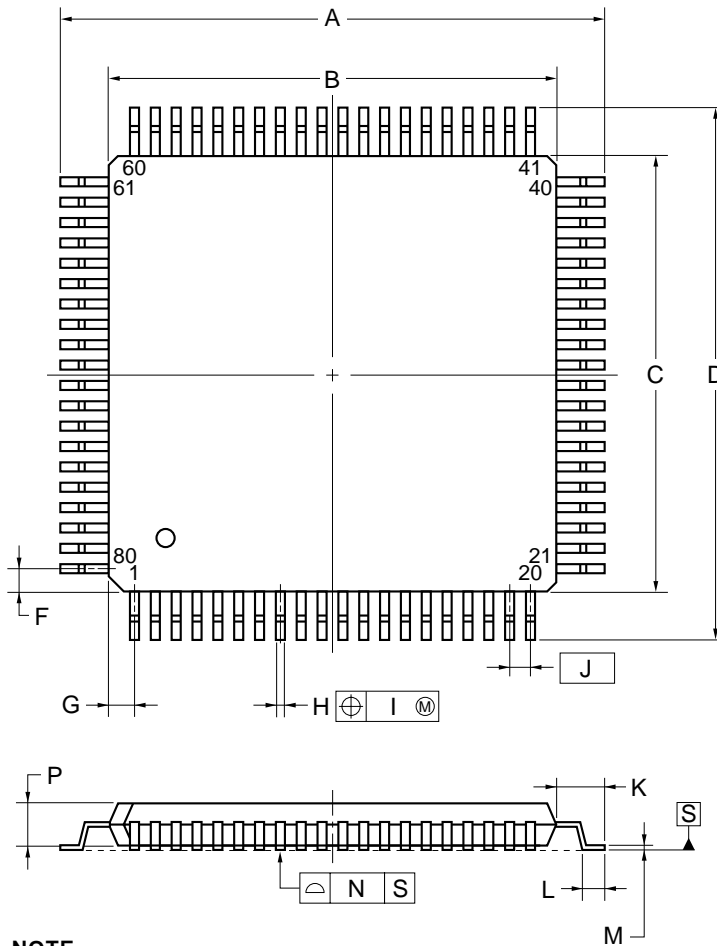


NOTE
 Each lead centerline is located within 0.13 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
A	17.2±0.4
B	14.0±0.2
C	14.0±0.2
D	17.2±0.4
F	0.825
G	0.825
H	0.30±0.10
I	0.13
J	0.65 (T.P.)
K	1.6±0.2
L	0.8±0.2
M	0.15 ^{+0.10} _{-0.05}
N	0.10
P	2.7±0.1
Q	0.1±0.1
R	5°±5°
S	3.0 MAX.

S80GC-65-3B9-6

★ 80-PIN PLASTIC QFP (14x14)



detail of lead end

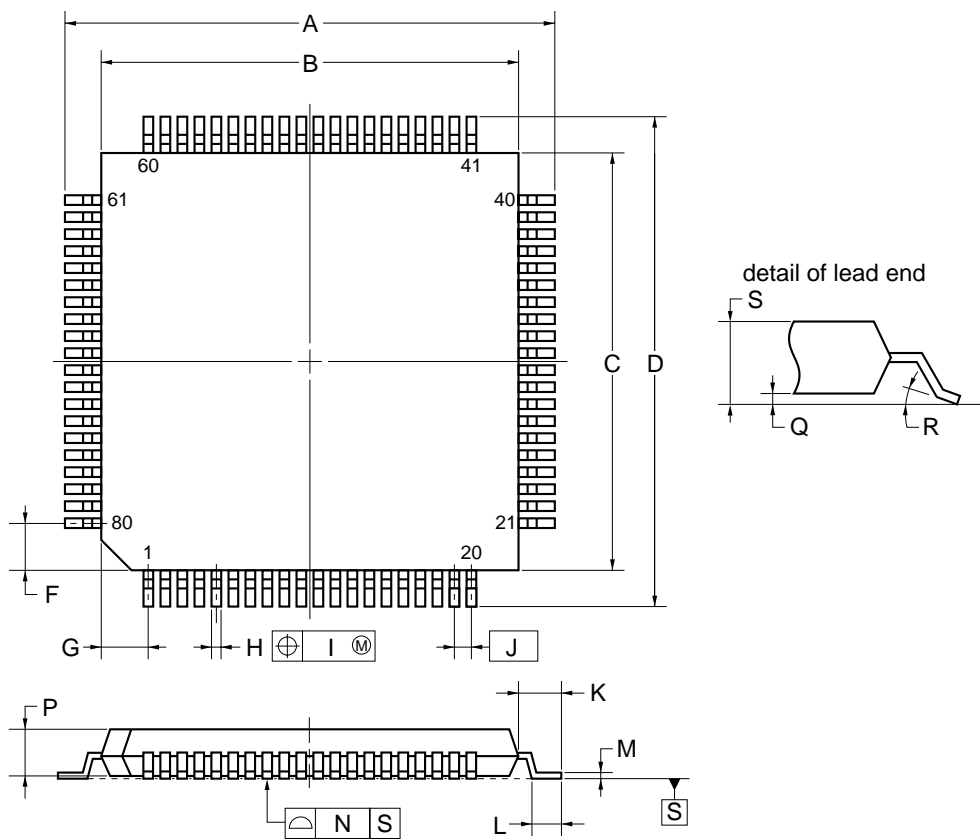
NOTE

Each lead centerline is located within 0.13 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
A	17.20±0.20
B	14.00±0.20
C	14.00±0.20
D	17.20±0.20
F	0.825
G	0.825
H	0.32±0.06
I	0.13
J	0.65 (T.P.)
K	1.60±0.20
L	0.80±0.20
M	0.17 ^{+0.03} _{-0.07}
N	0.10
P	1.40±0.10
Q	0.125±0.075
R	3° ^{+7°} _{-3°}
S	1.70 MAX.

P80GC-65-8BT-1

80 PIN PLASTIC TQFP (FINE PITCH) (12x12)



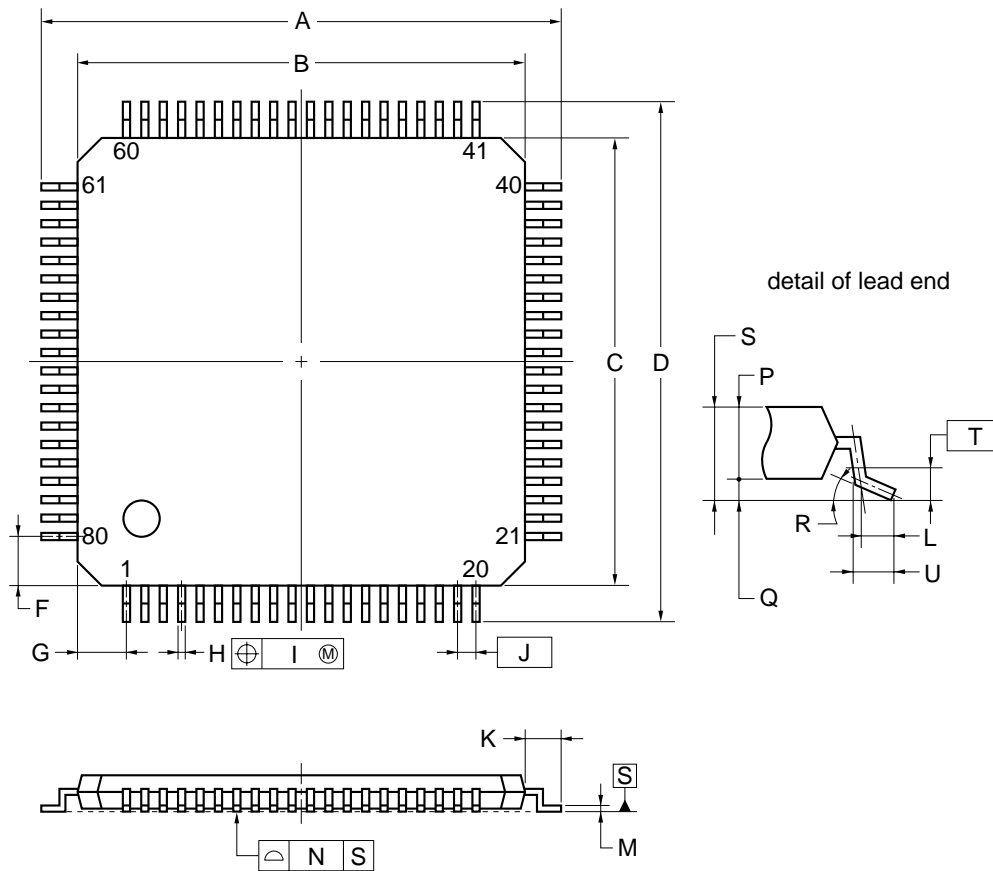
NOTE

Each lead centerline is located within 0.10 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
A	14.00±0.20
B	12.00±0.20
C	12.00±0.20
D	14.00±0.20
F	1.25
G	1.25
H	0.22 ^{+0.05} _{-0.04}
I	0.10
J	0.50 (T.P.)
K	1.00±0.20
L	0.50±0.20
M	0.145 ^{+0.055} _{-0.045}
N	0.10
P	1.05±0.07
Q	0.10±0.05
R	5°±5°
S	1.27 MAX.

P80GK-50-BE9-6

★ 80-PIN PLASTIC TQFP (FINE PITCH) (12x12)



NOTE

Each lead centerline is located within 0.08 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
A	14.0±0.2
B	12.0±0.2
C	12.0±0.2
D	14.0±0.2
F	1.25
G	1.25
H	0.22±0.05
I	0.08
J	0.5 (T.P.)
K	1.0±0.2
L	0.5
M	0.145±0.05
N	0.08
P	1.0
Q	0.1±0.05
R	3°+4° -3°
S	1.1±0.1
T	0.25
U	0.6±0.15

P80GK-50-9EU-1

15. RECOMMENDED SOLDERING CONDITIONS

Solder the μPD753017A under the following recommended conditions.

For the details on the recommended soldering conditions, refer to Information Document **Semiconductor Device Mounting Technology Manual (C10535E)**.

For the soldering methods and conditions other than those recommended, consult NEC.

Table 15-1. Soldering Conditions of Surface Mount Type (1/2)

- (1) μPD753012AGC-XXX-3B9: 80-pin plastic QFP (14 × 14 mm, resin thickness 2.7 mm)
- μPD753016AGC-XXX-3B9: 80-pin plastic QFP (14 × 14 mm, resin thickness 2.7 mm)
- μPD753017AGC-XXX-3B9: 80-pin plastic QFP (14 × 14 mm, resin thickness 2.7 mm)

Soldering Method	Soldering Conditions	Symbol
Infrared reflow	Package peak temperature: 235°C, Reflow time: 30 seconds or below (210°C or higher), Number of reflow processes: 3 max.	IR35-00-3
VPS	Package peak temperature: 215°C, Reflow time: 40 seconds or below (200°C or higher), Number of reflow processes: 3 max.	VP15-00-3
Wave soldering	Solder temperature: 260°C or below, Time: 10 seconds or below, Number of flow processes: 1 Preheating temperature: 120°C or below (package surface temperature)	WS60-00-1
Partial heating	Pin temperature: 300°C or below, Time: 3 seconds or below (per side of device)	–

- ★ (2) μPD753012AGC-XXX-8BT: 80-pin plastic QFP (14 × 14 mm, resin thickness 1.4 mm)
- μPD753016AGC-XXX-8BT: 80-pin plastic QFP (14 × 14 mm, resin thickness 1.4 mm)
- μPD753017AGC-XXX-8BT: 80-pin plastic QFP (14 × 14 mm, resin thickness 1.4 mm)

Soldering Method	Soldering Conditions	Symbol
Infrared reflow	Package peak temperature: 235°C, Reflow time: 30 seconds or below (210°C or higher), Number of reflow processes: 2 max.	IR35-00-2
VPS	Package peak temperature: 215°C, Reflow time: 40 seconds or below (200°C or higher), Number of reflow processes: 2 max.	VP15-00-2
Wave soldering	Solder temperature: 260°C or below, Time: 10 seconds or below, Number of flow processes: 1 Preheating temperature: 120°C or below (package surface temperature)	WS60-00-1
Partial heating	Pin temperature: 300°C or below, Time: 3 seconds or below (per side of device)	–

Caution Do not use two or more soldering methods in combination (except the partial heating method).

Table 15-1. Soldering Conditions of Surface Mount Type (2/2)

- (3) μPD753012AGK-XXX-BE9: 80-pin plastic TQFP (fine pitch) (12 × 12 mm, resin thickness 1.05 mm)
- μPD753016AGK-XXX-BE9: 80-pin plastic TQFP (fine pitch) (12 × 12 mm, resin thickness 1.05 mm)
- μPD753017AGK-XXX-BE9: 80-pin plastic TQFP (fine pitch) (12 × 12 mm, resin thickness 1.05 mm)

Soldering Method	Soldering Conditions	Symbol
Infrared reflow	Package peak temperature: 235°C, Reflow time: 30 seconds or below (210°C or higher), Number of reflow processes: 3 max., Exposure limit: 7 days ^{Note} (After that, prebaking is necessary at 125°C for 10 hours.)	IR35-107-3
VPS	Package peak temperature: 215°C, Reflow time: 40 seconds or below (200°C or higher), Number of reflow processes: 3 max., Exposure limit: 7 days ^{Note} (After that, prebaking is necessary at 125°C for 10 hours.)	VP15-107-3
Partial heating	Pin temperature: 300°C or below, Time: 3 seconds or below (per side of device)	–

Note The number of days for storage after the dry pack has been opened. The storage conditions are 25°C, 65% RH max.

- ★ (4) μPD753012AGK-XXX-9EU: 80-pin plastic TQFP (fine pitch) (12 × 12 mm, resin thickness 1.00 mm)
- μPD753016AGK-XXX-9EU: 80-pin plastic TQFP (fine pitch) (12 × 12 mm, resin thickness 1.00 mm)
- μPD753017AGK-XXX-9EU: 80-pin plastic TQFP (fine pitch) (12 × 12 mm, resin thickness 1.00 mm)

Soldering Method	Soldering Conditions	Symbol
Infrared reflow	Package peak temperature: 235°C, Reflow time: 30 seconds or below (210°C or higher), Number of reflow processes: 2 max., Exposure limit: 7 days ^{Note} (After that, prebaking is necessary at 125°C for 10 hours.)	IR35-107-2
VPS	Package peak temperature: 215°C, Reflow time: 40 seconds or below (200°C or higher), Number of reflow processes: 2 max., Exposure limit: 7 days ^{Note} (After that, prebaking is necessary at 125°C for 10 hours.)	VP15-107-2
Partial heating	Pin temperature: 300°C or below, Time: 3 seconds or below (per side of device)	–

Note The number of days for storage after the dry pack has been opened. The storage conditions are 25°C, 65% RH max.

Caution Do not use two or more soldering methods in combination (except the partial heating method).

APPENDIX A. μPD75316B, 753017A AND 75P3018A FUNCTION LIST

Parameter		μPD75316B	μPD753017A	μPD75P3018A
Program memory		Mask ROM 0000H-3F7FH (16256 × 8 bits)	Mask ROM 0000H-5FFFH (24576 × 8 bits)	One-time PROM 0000H-7FFFH (32768 × 8 bits)
Data memory		000H-3FFH (1024 × 4 bits)		
CPU		75X Standard	75XL CPU	
Instruction execution time	When main system clock is selected	0.95, 1.91, 15.3 μs (at 4.19 MHz operation)	<ul style="list-style-type: none"> • 0.95, 1.91, 3.81, 15.3 μs (at 4.19 MHz operation) • 0.67, 1.33, 2.67, 10.7 μs (at 6.0 MHz operation) 	
	When subsystem clock is selected	122 μs (32.768 kHz operation)		
Pin connection	44	P12/INT2	P12/INT2/TI1/TI2	
	47	P21	P21/PTO1	
	48	P22/PCL	P22/PCL/PTO2	
	50-53	P30-P33		P30/MD0-P33/MD3
	57	IC		V _{PP}
Stack	SBS register	None	SBS.3 = 1: Mk I mode selection SBS.3 = 0: Mk II mode selection	
	Stack area	000H-0FFH	n00H-nFFH (n = 0-3)	
	Subroutine call instruction stack operation	2-byte stack	Mk I mode: 2-byte stack Mk II mode: 3-byte stack	
Instruction	BRA !addr1 CALLA !addr1	Unavailable	Mk I mode: unavailable Mk II mode: available	
	MOVT XA, @BCDE MOVT XA, @BCXA BR BCDE BR BCXA		Available	
	CALL !addr	3 machine cycles	Mk I mode: 3 machine cycles, Mk II mode: 4 machine cycles	
	CALLF !faddr	2 machine cycles	Mk I mode: 2 machine cycles, Mk II mode: 3 machine cycles	
Timer		3 channels <ul style="list-style-type: none"> • Basic interval timer: 1 channel • 8-bit timer/event counter: 1 channel • Watch timer: 1 channel 	5 channels <ul style="list-style-type: none"> • Basic interval timer/watchdog timer: 1 channel • 8-bit timer/event counter: 3 channels (can be used as 16-bit timer/event counter, carrier generator, timer with gate) • Watch timer: 1 channel 	

Parameter		μPD75316B	μPD753017A	μPD75P3018A
Clock output (PCL)		Φ, 524, 262, 65.5 kHz (Main system clock: at 4.19 MHz operation)	<ul style="list-style-type: none"> • Φ, 524, 262, 65.5 kHz (Main system clock: at 4.19 MHz operation) • Φ, 750, 375, 93.8 kHz (Main system clock: at 6.0 MHz operation) 	
BUZ output		2 kHz (Main system clock: at 4.19 MHz operation)	<ul style="list-style-type: none"> • 2, 4, 32 kHz (Main system clock: at 4.19 MHz operation or subsystem clock: at 32.768 kHz operation) • 2.93, 5.86, 46.9 kHz (Main system clock: at 6.0 MHz operation) 	
Serial interface		3 modes are available <ul style="list-style-type: none"> • 3-wire serial I/O mode ... MSB/LSB can be selected for transfer first bit • 2-wire serial I/O mode • SBI mode 		
SOS register	Feedback resistor cut flag (SOS.0)	None	Provided	
	Sub-oscillator current cut flag (SOS.1)	None	Provided	
Register bank selection register (RBS)		None	Yes	
Standby release by INT0		Unavailable	Available	
Interrupt priority selection register (IPS)		None	Yes	
Vectored interrupt		External: 3, internal: 3	External: 3, internal: 5	
Supply voltage		V _{DD} = 2.0 to 6.0 V	V _{DD} = 1.8 to 5.5 V	
Operating ambient temperature		T _A = -40 to +85°C		
Package		<ul style="list-style-type: none"> • 80-pin plastic TQFP (fine pitch) (12 × 12 mm) • 80-pin plastic QFP (14 × 14 mm) 		

APPENDIX B. DEVELOPMENT TOOLS

The following development tools are provided for system development using the μPD753017A. The 75XL series uses a common relocatable assembler, in combination with a device file matching each machine.

Language processor

RA75X relocatable assembler	Host Machine	OS	Supply media	Part Number (product name)
	PC-9800 series	MS-DOS™ (Ver. 3.30 to Ver. 6.2 ^{Note})	3.5-inch 2HD	
IBM PC/AT™ and compatible machines	Refer to OS for IBM PC	3.5-inch 2HC	μS7B13RA75X	

Device file	Host Machine	OS	Supply media	Part Number (product name)
	PC-9800 series	MS-DOS (Ver. 3.30 to Ver. 6.2 ^{Note})	3.5-inch 2HD	
IBM PC/AT and compatible machines	Refer to OS for IBM PC	3.5-inch 2HC	μS7B13DF753017	

Note Ver. 5.00 or later is provided with a task swap function, but it does not work with this software.

Remark The operation of the assembler and device file is guaranteed only on the above host machines and OSs.

PROM write tools

★ ★	Hardware	PG-1500	PG-1500 is a PROM programmer which enables you to program single-chip microcontroller containing PROM by stand-alone or host machine operation by connecting an attached board and optional programmer adapter to PG-1500. It also enables you to program typical PROM devices of 256K bits to 4M bits.		
		PA-75P316BGC	PROM programmer adapter common to μPD75P3018GC-3B9. Connect the programmer adapter to PG-1500 for use.		
		PA-75P316BGK	PROM programmer adapter common to μPD75P3018GK-BE9. Connect the programmer adapter to PG-1500 for use.		
		PA-75P3018AGC-8BT	PROM programmer adapter common to μPD75P3018AGC-8BT. Connect the programmer adapter to PG-1500 for use.		
		PA-75P3018AGK-9EU	PROM programmer adapter common to μPD75P3018AGK-9EU. Connect the programmer adapter to PG-1500 for use.		
Software	PG-1500 controller	PG-1500 and a host machine are connected by serial and parallel interfaces and PG-1500 is controlled on the host machine.			
		Host machine	OS	Supply media	Part number (product name)
		PC-9800 series	MS-DOS (Ver. 3.30 to Ver. 6.2 ^{Note})	3.5-inch 2HD	μS5A13PG1500
		IBM PC/AT and compatible machines	Refer to OS for IBM PC	3.5-inch 2HD	μS7B13PG1500

Note Ver.5.00 or later is provided with a task swap function, but it does not work with this software.

Remark The operation of the PG-1500 controller is guaranteed only on the above host machines and OSs.

Debugging tool

The in-circuit emulators (IE-75000-R and IE-75001-R) are available as the program debugging tool for the μPD753017A.

The system configurations are described as follows.

Hardware	IE-75000-R ^{Note 1}	In-circuit emulator for debugging the hardware and software when developing the application systems that use the 75X series and 75XL series. When developing a μPD753017 subseries, the emulation board IE-75300-R-EM and emulation probe that are sold separately must be used with the IE-75000-R. By connecting with the host machine and the PROM programmer, efficient debugging can be made. It contains the emulation board IE-75000-R-EM which is connected.			
	IE-75001-R	In-circuit emulator for debugging the hardware and software when developing the application systems that use the 75X series and 75XL series. When developing a μPD753017 subseries, the emulation board IE-75300-R-EM and emulation probe which are sold separately must be used with the IE-75001-R. It can debug the system efficiently by connecting the host machine and PROM programmer.			
	IE-75300-R-EM	Emulation board for evaluating the application systems that use the μPD753017 subseries. It must be used with the IE-75000-R or IE-75001-R.			
	EP-753017GC-R	Emulation probe for the μPD753017AGC. It must be connected to the IE-75000-R (or IE-75001-R) and IE-75300-R-EM. It is supplied with the 80-pin conversion socket EV-9200GC-80 which facilitates connection to a target system.			
	EV-9200GC-80				
	EP-753017GK-R	Emulation probe for the μPD753017AGK. It must be connected to the IE-75000-R (or IE-75001-R) and IE-75300-R-EM. It is supplied with the 80-pin conversion adapter TGK-080SDW which facilitates connection to a target system.			
TGK-080SDW ^{Note 2}					
Software	IE control program	Connects the IE-75000-R or IE-75001-R to a host machine via RS-232-C and Centronix I/F and controls the IE-75000-R or IE-75001-R on a host machine.			
		Host machine	OS	Supply media	Part number (product name)
		PC-9800 series	MS-DOS (Ver. 3.30 to Ver. 6.2 ^{Note 3})	3.5-inch 2HD	μS5A13IE75X
				5-inch 2HD	μS5A10IE75X
		IBM PC/AT and compatible machines	Refer to OS for IBM PC	3.5-inch 2HC	μS7B13IE75X
5-inch 2HC	μS7B10IE75X				

★

Notes 1. Maintenance parts

2. This is a product of TOKYO ELETECH CORPORATION.

For further information, contact: Daimaru Kogyo, Ltd.

Tokyo Electronics Department (TEL +81-3-3820-7112)

Osaka Electronics 2nd Department (TEL +81-6-6244-6672)

3. Ver.5.00 or later is provided with a task swap function, but it dose not work with this software.

Remarks 1. The operation of the IE control program is guaranteed only on the above host machines and OSs.

2. The μPD753012, 753016, 753017, 75P3018, 753012A, 753016A, 753017A, and 75P3018A are commonly referred to as the μPD753017 subseries.

OS for IBM PC

The following IBM PC OS's are supported.

OS	Version
PC DOS™	Ver. 5.02 to Ver. 6.3 J6.1/V ^{Note} to J6.3/V ^{Note}
MS-DOS	Ver. 5.0 to Ver. 6.22 5.0/V ^{Note} to 6.2/V ^{Note}
IBM DOS™	J5.02/V ^{Note}

Note Only English version is supported.

Caution Ver. 5.0 or later is provided with a task swap function, but it does not work with this software.

★ APPENDIX C. RELATED DOCUMENTS

The related documents indicated in this publication may include preliminary versions. However, preliminary versions are not marked as such.

Device Related Documents

Document Name	Document No.	
	Japanese	English
μPD753012A, 753016A, 753017A Data Sheet	U11662J	U11662E (this document)
μPD75P3018A Data Sheet	U11917J	U11917E
μPD753017 User's Manual	U11282J	U11282E
μPD753017 Instruction Table	IEM-5598	—
75XL Series Selection Guide	U10453J	U10453E

Development Tool Related Documents

Document Name		Document No.		
		Japanese	English	
Hardware	IE-75000-R/IE-75001-R User's Manual		EEU-846	EEU-1416
	IE-75300-R-EM User's Manual		U11354J	EEU-1493
	EP-753017GC/GK-R User's Manual		EEU-967	EEU-1495
	PG-1500 User's Manual		U11940J	U11940E
Software	RA75X Assembler Package User's Manual	Operation	U12622J	U12622E
		Language	U12385J	U12385E
	PG-1500 Controller User's Manual	PC-9800 Series (MS-DOS) Base	EEU-704	EEU-1291
		IBM PC Series (PC DOS) Base	EEU-5008	U10540E

Other Related Documents

Document Name	Document No.	
	Japanese	English
SEMICONDUCTOR SELECTION GUIDE Products & Package (CD-ROM)	X13769X	
Semiconductor Device Mounting Technology Manual	C10535J	C10535E
Quality Grades on NEC Semiconductor Devices	C11531J	C11531E
NEC Semiconductor Device Reliability/Quality Control System	C10983J	C10983E
Guide to Prevent Damage for Semiconductor Devices by Electrostatic Discharge (ESD)	C11892J	C11892E
Guide to Microcontroller-Related Products by Third Parties	U11416J	—

Caution The above related documents are subject to change without notice. For design purpose, etc., be sure to use the latest documents.

NOTES FOR CMOS DEVICES**① PRECAUTION AGAINST ESD FOR SEMICONDUCTORS**

Note:

Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

② HANDLING OF UNUSED INPUT PINS FOR CMOS

Note:

No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note:

Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

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- Product release schedule
- Availability of related technical literature
- Development environment specifications (for example, specifications for third-party tools and components, host computers, power plugs, AC supply voltages, and so forth)
- Network requirements

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(Note)

- (1) "NEC" as used in this statement means NEC Corporation and also includes its majority-owned subsidiaries.
- (2) "NEC semiconductor products" means any semiconductor product developed or manufactured by or for NEC (as defined above).